

HP ProLiant ML350p Gen8 Server Maintenance and Service Guide

Abstract

This document is for the person who installs, administers, and troubleshoots servers and storage systems. This document is intended for experienced IT professionals or end-users with no or prior hardware setup experience. HP assumes you are qualified in the servicing of computer equipment and trained in recognizing hazards in products with hazardous energy levels.



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Customer self repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

NOTE: Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

Parts only warranty service

Your HP Limited Warranty may include a parts only warranty service. Under the terms of parts only warranty service, HP will provide replacement parts free of charge.

For parts only warranty service, CSR part replacement is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

REMARQUE: Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agréé local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

Service de garantie "pièces seules"

Votre garantie limitée HP peut inclure un service de garantie "pièces seules". Dans ce cas, les pièces de rechange fournies par HP ne sont pas facturées.

Dans le cadre de ce service, la réparation des pièces CSR par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

Obbligatorie – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

Opzionali – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

NOTA: alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

Servizio di garanzia per i soli componenti

La garanzia limitata HP può includere un servizio di garanzia per i soli componenti. Nei termini di garanzia del servizio per i soli componenti, HP fornirà gratuitamente le parti di ricambio.

Per il servizio di garanzia per i soli componenti è obbligatoria la formula CSR che prevede la riparazione da parte del cliente. Se il cliente invece richiede la sostituzione ad HP, dovrà sostenere le spese di spedizione e di manodopera per il servizio.

Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

Zwingend – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Optional – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

HINWEIS: Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das

defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

Parts-only Warranty Service (Garantieservice ausschließlich für Teile)

Ihre HP Garantie umfasst möglicherweise einen Parts-only Warranty Service (Garantieservice ausschließlich für Teile). Gemäß den Bestimmungen des Parts-only Warranty Service stellt HP Ersatzteile kostenlos zur Verfügung.

Für den Parts-only Warranty Service ist das CSR-Verfahren zwingend vorgegeben. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

NOTA: Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no

enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

Servicio de garantía exclusivo de componentes

La garantía limitada de HP puede que incluya un servicio de garantía exclusivo de componentes. Según las condiciones de este servicio exclusivo de componentes, HP le facilitará los componentes de repuesto sin cargo adicional alguno.

Para este servicio de garantía exclusivo de componentes, es obligatoria la sustitución de componentes por parte del usuario (CSR). Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

Verplicht: Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Optioneel: Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

OPMERKING: Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

Garantieservice "Parts Only"

Het is mogelijk dat de HP garantie alleen de garantieservice "Parts Only" omvat. Volgens de bepalingen van de Parts Only garantieservice zal HP kosteloos vervangende onderdelen ter beschikking stellen.

Voor de Parts Only garantieservice is vervanging door CSR-onderdelen verplicht. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

Obrigatória – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

OBSERVAÇÃO: Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP (<http://www.hp.com/go/selfrepair>).

Serviço de garantia apenas para peças

A garantia limitada da HP pode incluir um serviço de garantia apenas para peças. Segundo os termos do serviço de garantia apenas para peças, a HP fornece as peças de reposição sem cobrar nenhuma taxa.

No caso desse serviço, a substituição de peças CSR é obrigatória. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

カスタマーセルフリペア

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数のCSR部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- **必須** - カスタマーセルフリペアが必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- **任意** - カスタマーセルフリペアが任意である部品。この部品もカスタマーセルフリペア用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

注： HP製品の一部の部品は、カスタマーセルフリペア用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品がカスタマーセルフリペア除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口にご電話いただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。カスタマーセルフリペアの際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

部品のみ保証サービス

HP保証サービスには、部品のみ保証サービスが適用される場合があります。このサービスでは、交換部品は無償で提供されます。

部品のみ保証サービスにおいては、CSR部品をお客様により交換作業していただくことが必須となります。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費はお客様の負担となります。

客户自行维修

HP 产品提供许多客户自行维修 (CSR) 部件，以尽可能缩短维修时间和在更换缺陷部件方面提供更大的灵活性。如果在诊断期间 HP（或 HP 服务提供商或服务合作伙伴）确定可以通过使用 CSR 部件完成维修，HP 将直接把该部件发送给您进行更换。有两类 CSR 部件：

- **强制性的** — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。
- **可选的** — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

注：某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

CSR 部件将在下一个工作日发运（取决于备货情况和允许的地理范围）。在允许的地理范围内，可在当天或四小时内发运，但要收取额外费用。如果需要帮助，您可以致电 HP 技术支持中心，将会有技术人员通过电话为您提供帮助。HP 会在随更换的 CSR 部件发运的材料中指明是否必须将有缺陷的部件返还给 HP。如果要求您将有缺陷的部件返还给 HP，那么您必须在规定期限内（通常是五 (5) 个工作日）将缺陷部件发给 HP。有缺陷的部件必须随所提供的发运材料中的相关文件一起返还。如果未能送还有缺陷的部件，HP 可能会要求您支付更换费用。客户自行维修时，HP 将承担所有相关运输和部件返回费用，并指定快递商/承运商。

有关 HP 客户自行维修计划的详细信息，请与您当地的服务提供商联系。有关北美地区的计划，请访问 HP 网站 (<http://www.hp.com/go/selfrepair>)。

仅部件保修服务

您的 HP 有限保修服务可能涉及仅部件保修服务。根据仅部件保修服务条款的规定，HP 将免费提供更换的部件。

仅部件保修服务要求进行 CSR 部件更换。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP (或 HP 服務供應商或維修夥伴) 辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

備註：某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

僅限零件的保固服務

您的「HP 有限保固」可能包含僅限零件的保固服務。在僅限零件的保固服務情況下，HP 將免費提供替換零件。

針對僅限零件的保固服務，CSR 零件替換是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 융통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

참고: 일부 HP 부품은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 만족스러운 고객 보증을 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다. 이러한 부품들은 Illustrated Parts Catalog에 "No"라고 표시되어 있습니다.

CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.

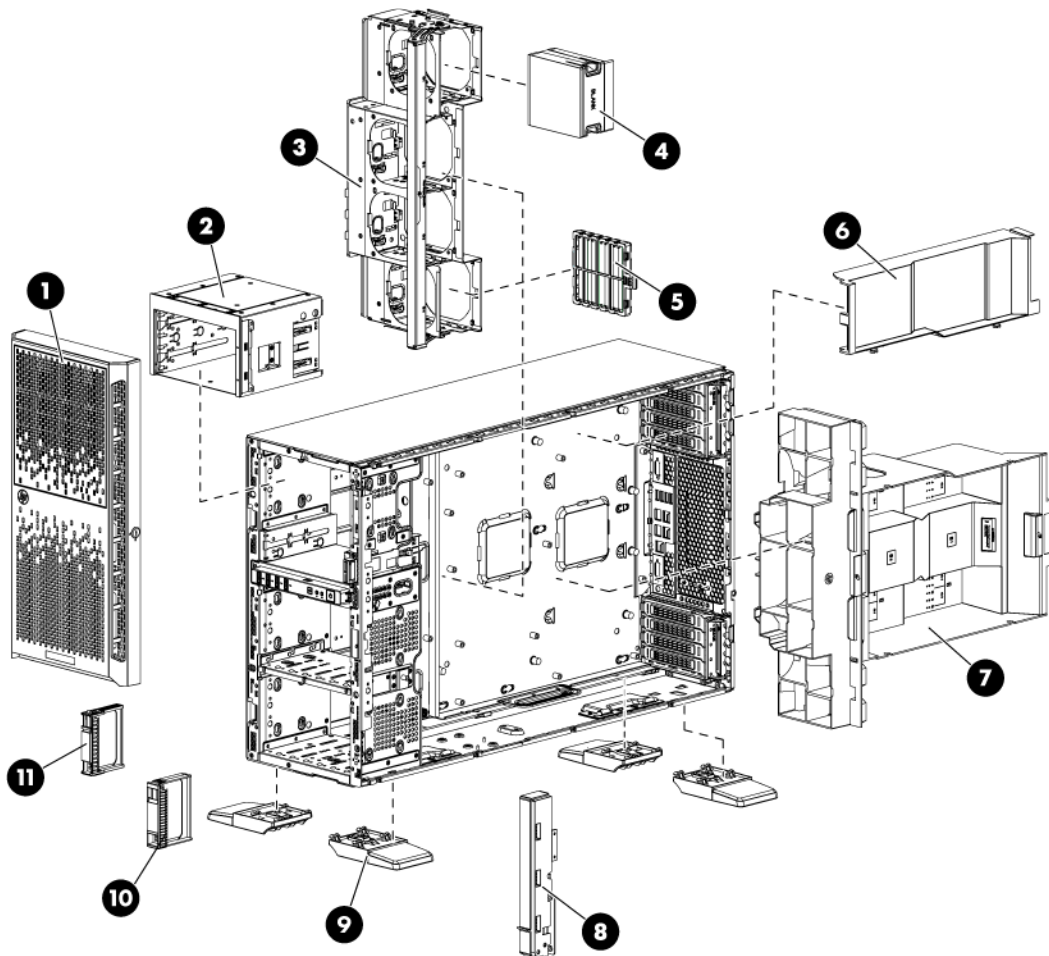
부품 제공 보증 서비스

HP 제한 보증에는 부품 제공 보증 서비스가 포함될 수 있습니다. 이러한 경우 HP는 부품 제공 보증 서비스의 조건에 따라 교체 부품만을 무료로 제공합니다.

부품 제공 보증 서비스 제공 시 CSR 부품 교체는 의무 사항입니다. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

Illustrated parts catalog

Mechanical components



Item	Description	Spare part number	Customer self repair (on page 5)
1	Front bezel	667267-001	Mandatory ¹
2	Second optical drive cage	670612-001	Optional ²
3	Fan cage	667255-001	Optional ²
4	Fan blank	667262-001	Mandatory ¹
5	Fan louver	667258-001	Optional ²
6	PCI air baffles (2)	667280-001	Mandatory ¹
7	System air baffle	667256-001	Mandatory ¹
8	Bezel ear kit	667274-001	Mandatory ¹
	a) Bezel ear, right	—	—
	b) Bezel ear, left*	—	—

Item	Description	Spare part number	Customer self repair (on page 5)
	c) T-10 screws (4)*	—	—
	d) T-15 screws (4)*	—	—
	e) Discovery service cable*	—	—
	f) Server baseblank covers (2)*	—	—
9	Tower feet	667264-001	Mandatory ¹
10	LFF drive blank	667279-001	Mandatory ¹
11	SFF drive blank	667276-001	Mandatory ¹
12	Drive cage blank*	667261-001	Mandatory ¹
13	Heatsink retaining levers*	751444-001	Mandatory ¹

*Not shown

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese addizionali a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional— componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra “No” en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garantieservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorzwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca “No” (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据为您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

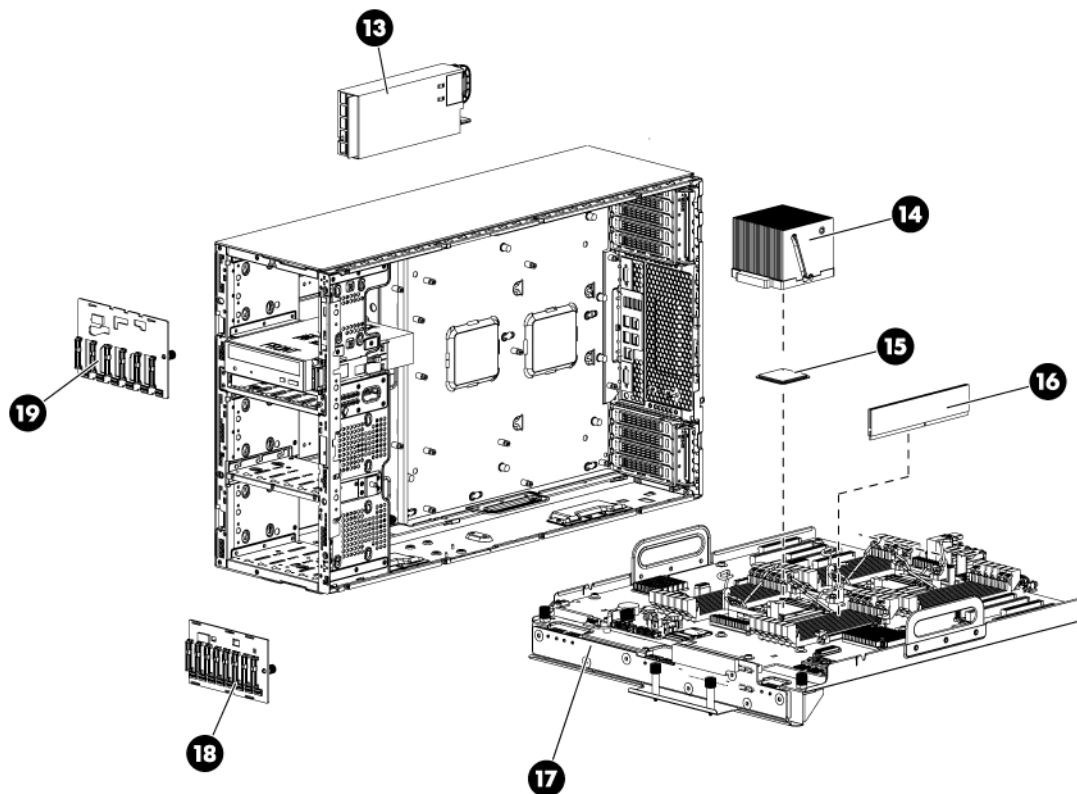
³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

System components



Item	Description	Spare part number	Customer self repair (on page 5)
13	Power supplies	—	—
	a) HP 460W CS Gold (92% efficiency)	511777-001	Mandatory ¹
	b) HP 460 W CS Platinum Plus (94% efficiency)*	660184-001	Mandatory ¹
	c) HP 750 W CS Gold (92% efficiency)*	511778-001	Mandatory ¹
	d) HP 750 W CS Platinum Plus (94% efficiency)*	660183-001	Mandatory ¹
	f) HP 1200 W CS Platinum Plus (94% efficiency)*	660185-001	Mandatory ¹
14	Heatsink	667268-001	Optional ²
15	Processors**	—	—
	a) 1.8 GHz Intel Xeon E5-2650L processor, 8C, 70 W	670534-001	Optional ²
	b) 1.8 GHz Intel Xeon E5-2603 processor, 4C, 80 W*	670533-001	Optional ²
	c) 1.8 GHz Intel Xeon E5-2603v2 processor, 4C, 80 W*	730243-001	Optional ²
	d) 2.0 GHz Intel Xeon E5-2650 processor, 8C, 95 W*	670526-001	Optional ²
	e) 2.0 GHz Intel Xeon E5-2630L processor, 6C, 60 W*	670535-001	Optional ²
	f) 2.0 GHz Intel Xeon E5-2620 processor, 6C, 95 W*	670529-001	Optional ²

Item	Description	Spare part number	Customer self repair (on page 5)
	g) 2.0 GHz Intel Xeon E5-2640v2 processor, 8C, 95 W*	730239-001	Optional ²
	h) 2.1 GHz Intel Xeon E5-2620v2 processor, 6C, 80 W*	730241-001	Optional ²
	i) 2.2 GHz Intel Xeon E5-2660 processor, 8C, 95 W*	670525-001	Optional ²
	j) 2.3GHz Intel Xeon E5-2630 processor, 6C, 95W*	670528-001	Optional ²
	k) 2.4 GHz Intel Xeon E5-2609 processor, 4C, 80 W*	670530-001	Optional ²
	l) 2.4 GHz Intel Xeon E5-2630L v2 processor, 6C, 60 W*	730244-001	Optional ²
	m) 2.4 GHz Intel Xeon E5-2665 processor, 8C, 115 W*	670524-001	Optional ²
	n) 2.5 GHz Intel Xeon E5-2640 processor, 6C, 95 W*	670527-001	Optional ²
	o) 2.5 GHz Intel Xeon E5-2670v2 processor, 10C, 115 W*	730236-001	Optional ²
	p) 2.5 GHz Intel Xeon E5-2609v2 processor, 4C, 80 W*	730242-001	Optional ²
	q) 2.6 GHz Intel Xeon E5-2670 processor, 8C, 115 W*	670523-001	Optional ²
	r) 2.6 GHz Intel Xeon E5-2650v2 processor, 8C, 95 W*	730238-001	Optional ²
	s) 2.6 GHz Intel Xeon E5-2630v2 processor, 8C, 80 W*	730240-001	Optional ²
	t) 2.7 GHz Intel Xeon E5-2680 processor, 8C, 130 W*	670522-001	Optional ²
	u) 2.7 GHz Intel Xeon E5-2697v2 processor, 12C, 130 W*	730245-001	Optional ²
	v) 2.8-GHz Intel Xeon processor E5-2680v2, 115W	730235-001	Optional ²
	w) 2.9 GHz Intel Xeon E5-2667 processor, 6C, 130 W*	670537-001	Optional ²
	x) 2.9 GHz Intel Xeon E5-2690 processor, 8C, 135 W*	670521-001	Optional ²
	y) 3.0 GHz Intel Xeon E5-2637 processor, 2C, 80 W	670539-001	Optional ²
	z) 3.0 GHz Intel Xeon E5-2690v2 processor, 10C, 130 W*	730234-001	Optional ²
	aa) 3.0 GHz Intel Xeon E5-2667v2 processor, 8C, 130 W*	730247-001	Optional ²
	bb) 3.3 GHz Intel Xeon E5-2643 processor, 4C, 130 W*	670538-001	Optional ²
	cc) 3.3 GHz Intel Xeon E5-2643v2 processor, 6C, 130 W*	730248-001	Optional ²
	dd) 3.5 GHz Intel Xeon E5-2637v2 processor, 4C, 130 W*	730249-001	Optional ²
16	DIMMs	—	—
	a) 2 GB, PC3L-10600E-9, single-rank x8	664694-001	Mandatory ¹
	b) 2 GB, PC3-14900E-13, single-rank x8	715269-001	Mandatory ¹

Item	Description	Spare part number	Customer self repair (on page 5)
	c) 2 GB, PC3L-12800E-11, single-rank x8	715279-001	Mandatory ¹
	d) 4 GB, PC3L-12800E-11, dual-rank x8	715280-001	Mandatory ¹
	e) 4 GB, PC3L-12800R-11, single-rank x4	715282-001	Mandatory ¹
	f) 4 GB, PC3-14900E-13, dual-rank x8	715270-001	Mandatory ¹
	g) 4 GB, PC3-14900R-13, single-rank x4	715272-001	Mandatory ¹
	h) 4 GB, PC3L-10600R-9, single-rank x4*	664688-001	Mandatory ¹
	i) 4 GB, PC3-12800R-11, single-rank x4*	664689-001	Mandatory ¹
	j) 4 GB, PC3L-10600E-9, dual-rank x8*	664695-001	Mandatory ¹
	k) 8 GB, PC3-12800R-11, single-rank x4*	664691-001	Mandatory ¹
	l) 8 GB, PC3L-10600R, dual-rank x4*	664690-001	Mandatory ¹
	m) 8 GB, PC3L-10600E, dual-rank x8*	664696-001	Mandatory ¹
	n) 8 GB, PC3L-12800E-11, dual-rank x8	715281-001	Mandatory ¹
	o) 8 GB, PC3L-12800R-11, dual-rank x4	715283-001	Mandatory ¹
	p) 8 GB, PC3L-12800R-11, single-rank x4	735302-001	Mandatory ¹
	q) 8 GB, PC3-14900E-13, dual-rank x8	715271-001	Mandatory ¹
	r) 8 GB, PC3-14900R-13, dual-rank x4	715273-001	Mandatory ¹
	s) 8 GB, PC3-14900R-13, single-rank x4	735303-001	Mandatory ¹
	t) 16 GB, PC3L-12800R-11, dual-rank x4	715284-001	Mandatory ¹
	u) 16 GB, PC3-14900R-13, dual-rank x4	715274-001	Mandatory ¹
	v) 16 GB, PC3L-10600R-9, dual-rank x4*	664692-001	Mandatory ¹
	w) 16 GB, PC3-12800R-11, dual-rank x4*	684031-001	Mandatory ¹
	x) 32 GB, PC3-14900L-13, quad-rank x4	715275-001	Mandatory ¹
	y) 32 GB, PC3L-10600L, quad-rank x4*	664693-001	Mandatory ¹
17	System board assembly	667253-001	Optional ²
18	SFF drive backplane	693610-001	Optional ²
19	LFF drive backplane	693611-001	Optional ²
20	Front I/O module assembly*	667260-001	Optional ²
21	SID module assembly*	667271-001	Optional ²
22	Miscellaneous cable kit	667266-001	Mandatory ¹
	a) Mini-SAS to Mini-SAS, 12.75-in*	—	—
	b) Drive backplane power cable*	—	—
	c) Graphic support cable, 2x4*	701539-001	—
23	Mini-SAS cables	—	—
	a) Mini-SAS cable, 35 in*	667277-001	Mandatory ¹
	b) Mini-SAS cable, 25.5 in*	498424-001	Mandatory ¹
24	Power cable*	667259-001	Optional ²

Item	Description	Spare part number	Customer self repair (on page 5)
25	SATA cable*	667265-001	Mandatory ¹
26	SFF drive backplane with expander*	693610-001	Optional ²
27	LFF drive backplane with expander*	693611-001	Optional ²
28	Fan module*	667254-002	Mandatory ¹
29	Bracket support holder*	667263-001	Mandatory ¹
	a) Right holder	—	—
	b) Left holder	—	—
30	Two-bay power supply backplane board* (with 2 T-15 screws)	667269-001	Optional ²
31	Four-bay power supply backplane board* (with 2 T-15 screws)	667281-001	Optional ²
32	Two-bay power supply blank*	667270-001	Mandatory ¹
33	Rail kit*	667272-001	Mandatory ¹
34	Rack bezel*	667273-001	Mandatory ¹
35	Power supply air baffle*	667257-001	Optional ²

*Not shown

**All processors in this HP ProLiant server must have the same cache size, speed, number of cores, and rated maximum power consumption.

¹Mandatory—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.

²Optional—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

³No—Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

¹Mandatory: Obligatoire—Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

²Optional: Facultatif—Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

³No: Non—Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

¹Mandatory: Obbligatorie—Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

²Optional: Opzionali—Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese addizionali a seconda del tipo di garanzia previsto per il prodotto.

³No: Non CSR—Alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

¹Mandatory: Zwingend—Teile, die im Rahmen des Customer Self Repair Programms ersetzt werden müssen. Wenn Sie diese Teile von HP ersetzen lassen, werden Ihnen die Versand- und Arbeitskosten für diesen Service berechnet.

²Optional: Optional—Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

³No: Kein—Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

¹Mandatory: Obligatorio—componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.

²Optional: Opcional— componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

³No: No—Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra “No” en el catálogo ilustrado de componentes.

¹Mandatory: Verplicht—Onderdelen waarvoor Customer Self Repair verplicht is. Als u HP verzoekt deze onderdelen te vervangen, komen de reiskosten en het arbeidsloon voor uw rekening.

²Optional: Optioneel—Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garanteservice voor het product.

³No: Nee—Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievooraarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

¹Mandatory: Obrigatória—Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

²Optional: Opcional—Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

³No: Nenhuma—Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca “No” (Não), no catálogo de peças ilustrado.

¹Mandatory : 必須 - 顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。

²Optional : 任意 - 顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、費用を負担していただくことなく保証サービスを受けることができます。

³No : 除外 - HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

¹Mandatory: 强制性的 — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。

²Optional: 可选的 — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

³No: 否 — 某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

¹Mandatory: 強制的 — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。

²Optional: 選購的 — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

³No: 否 — 某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

¹ Mandatory: 필수 — 고객 셀프 수리가 의무 사항인 필수 부품. 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.

² Optional: 옵션 — 고객 셀프 수리가 선택 사항인 부품. 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

³ No: No — 고객 셀프 수리가 불가능하도록 설계된 HP 부품. 이 부품들은 고객 셀프 수리가 불가능하도록 설계되었습니다. HP는 고객 보증을 만족시키기 위해 공인 서비스 제공업체를 통해 부품을 교체하도록 하고 있습니다.

Removal and replacement procedures

Required tools

You need the following items for some procedures:

- T-10 Torx screwdriver
- T-15 Torx screwdriver
- HP Insight Diagnostics software ("[HP Insight Diagnostics](#)" on page 75)

Safety considerations

Before performing service procedures, review all the safety information.

Preventing electrostatic discharge

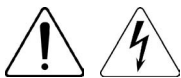
To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

Symbols on equipment

The following symbols may be placed on equipment to indicate the presence of potentially hazardous conditions.



This symbol indicates the presence of hazardous energy circuits or electric shock hazards. Refer all servicing to qualified personnel.

WARNING: To reduce the risk of injury from electric shock hazards, do not open this enclosure. Refer all maintenance, upgrades, and servicing to qualified personnel.



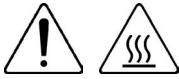
This symbol indicates the presence of electric shock hazards. The area contains no user or field serviceable parts. Do not open for any reason.

WARNING: To reduce the risk of injury from electric shock hazards, do not open this enclosure.



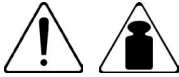
This symbol on an RJ-45 receptacle indicates a network interface connection.

WARNING: To reduce the risk of electric shock, fire, or damage to the equipment, do not plug telephone or telecommunications connectors into this receptacle.



This symbol indicates the presence of a hot surface or hot component. If this surface is contacted, the potential for injury exists.

WARNING: To reduce the risk of injury from a hot component, allow the surface to cool before touching.



This symbol indicates that the component exceeds the recommended weight for one individual to handle safely.

WARNING: To reduce the risk of personal injury or damage to the equipment, observe local occupational health and safety requirements and guidelines for manual material handling.



These symbols, on power supplies or systems, indicate that the equipment is supplied by multiple sources of power.

WARNING: To reduce the risk of injury from electric shock, remove all power cords to completely disconnect power from the system.

Rack warnings



WARNING: To reduce the risk of personal injury or damage to the equipment, be sure that:

- The leveling jacks are extended to the floor.
- The full weight of the rack rests on the leveling jacks.
- The stabilizing feet are attached to the rack if it is a single-rack installation.
- The racks are coupled together in multiple-rack installations.
- Only one component is extended at a time. A rack may become unstable if more than one component is extended for any reason.



WARNING: To reduce the risk of personal injury or equipment damage when unloading a rack:

- At least two people are needed to safely unload the rack from the pallet. An empty 42U rack can weigh as much as 115 kg (253 lb), can stand more than 2.1 m (7 ft) tall, and might become unstable when being moved on its casters.
- Never stand in front of the rack when it is rolling down the ramp from the pallet. Always handle the rack from both sides.



WARNING: To reduce the risk of personal injury or damage to the equipment, adequately stabilize the rack before extending a component outside the rack. Extend only one component at a time. A rack may become unstable if more than one component is extended.



WARNING: When installing a server in a telco rack, be sure that the rack frame is adequately secured at the top and bottom to the building structure.

Preparation procedures

To access some components and perform certain service procedures, you must perform one or more of the following procedures:

- Power down the server (on page 26).
If you must remove a server from a rack or a non-hot-plug component from a server, power down the server.
- Remove the tower bezel (on page 27).
- Remove the rack bezel.
- Extend the server from the rack (on page 28).
If you are performing service procedures in an HP, Compaq branded, telco, or third-party rack cabinet, you can use the locking feature of the rack rails to support the server and gain access to internal components.
For more information about telco rack solutions, refer to the RackSolutions.com website (<http://www.racksolutions.com/hp>).

Power up the server

To power up the server:

1. Connect each power cord to the server.
2. Connect each power cord to the power source.
3. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

Power down the server

Before powering down the server for any upgrade or maintenance procedures, perform a backup of critical server data and programs.



IMPORTANT: When the server is in standby mode, auxiliary power is still being provided to the system.

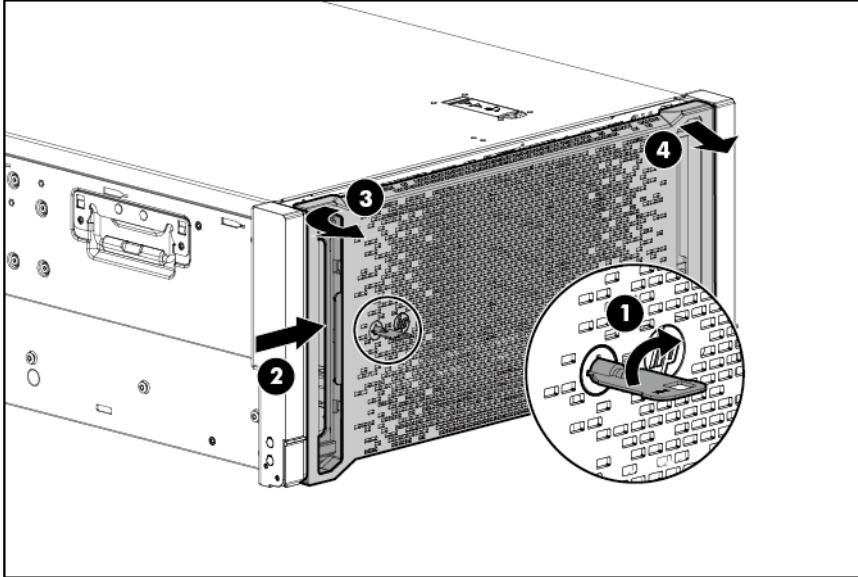
To power down the server, use one of the following methods:

- Press and release the Power On/Standby button.
This method initiates a controlled shutdown of applications and the OS before the server enters standby mode.
- Press and hold the Power On/Standby button for more than 4 seconds to force the server to enter standby mode.
This method forces the server to enter standby mode without properly exiting applications and the OS. If an application stops responding, you can use this method to force a shutdown.
- Use a virtual power button selection through iLO 4.
This method initiates a controlled remote shutdown of applications and the OS before the server enters standby mode.

Before proceeding, verify the server is in standby mode by observing that the system power LED is amber.

Remove the security bezel

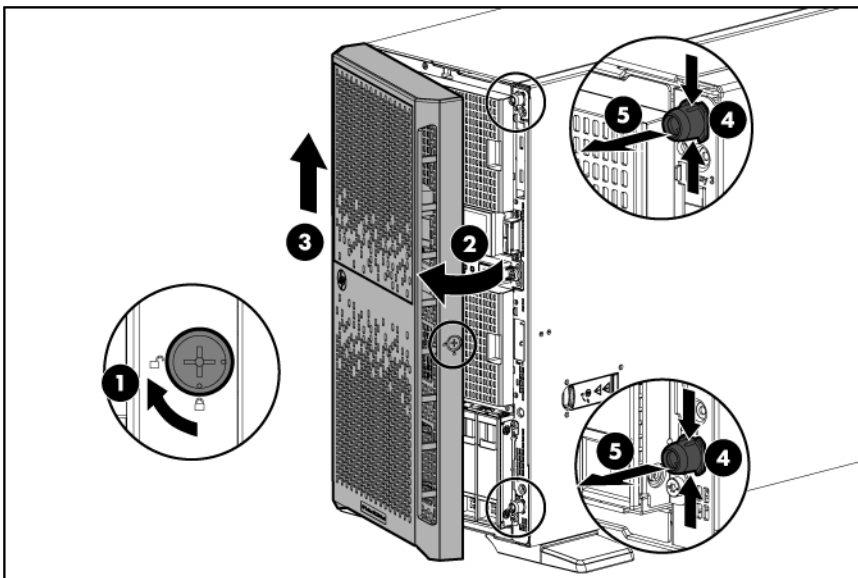
Unlock the security bezel, press the latch on the security bezel, and then remove the security bezel.



Remove the tower bezel

This server has a removable bezel that must be unlocked and opened before accessing the hard drives. The bezel must be kept closed during normal server operations.

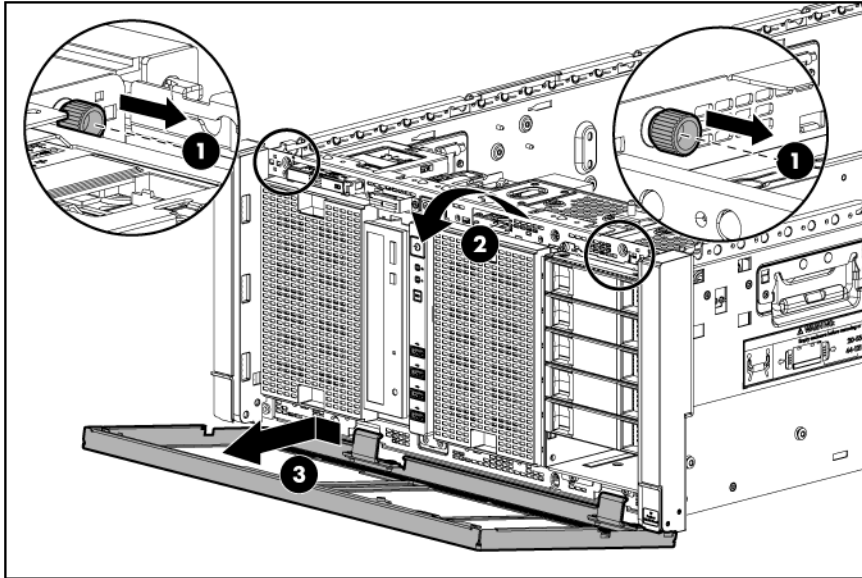
1. Using the key provided with the server, unlock the bezel with a clockwise turn.
2. Remove the tower bezel.



Remove the rack bezel

1. If installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).

3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Extend the server from the rack (on page 28).
5. Remove the access panel ("Access panel" on page 29).
6. Loosen the rack bezel thumbscrews located inside the chassis.
7. Remove the rack bezel.



Extend the server from the rack



IMPORTANT: If the server is installed in a telco rack, remove the server from the rack to access internal components.

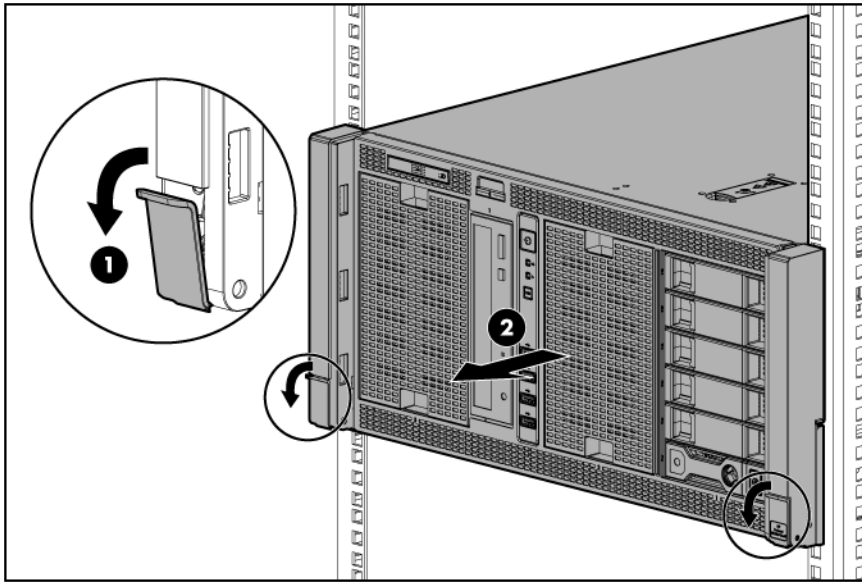
1. Pull down the quick release levers on each side of the server.
2. Extend the server from the rack.



WARNING: To reduce the risk of personal injury or equipment damage, be sure that the rack is adequately stabilized before extending a component from the rack.



WARNING: To reduce the risk of personal injury, be careful when pressing the server rail-release latches and sliding the server into the rack. The sliding rails could pinch your fingers.



3. After performing the installation or maintenance procedure, slide the server back into the rack, and then press the server firmly into the rack to secure it in place.

⚠ WARNING: To reduce the risk of personal injury, be careful when pressing the server rail-release latches and sliding the server into the rack. The sliding rails could pinch your fingers.

Access panel

⚠ WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

⚠ CAUTION: Do not operate the server for long periods with the access panel open or removed. Operating the server in this manner results in improper airflow and improper cooling that can lead to thermal damage.

To remove the component:

1. Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - For tower models, place the server on a flat, level surface with the access panel facing up.
 - For rack models, extend the server from the rack (on page 28).
5. Open the locking latch, slide the access panel to the rear of the chassis, and then remove the access panel.

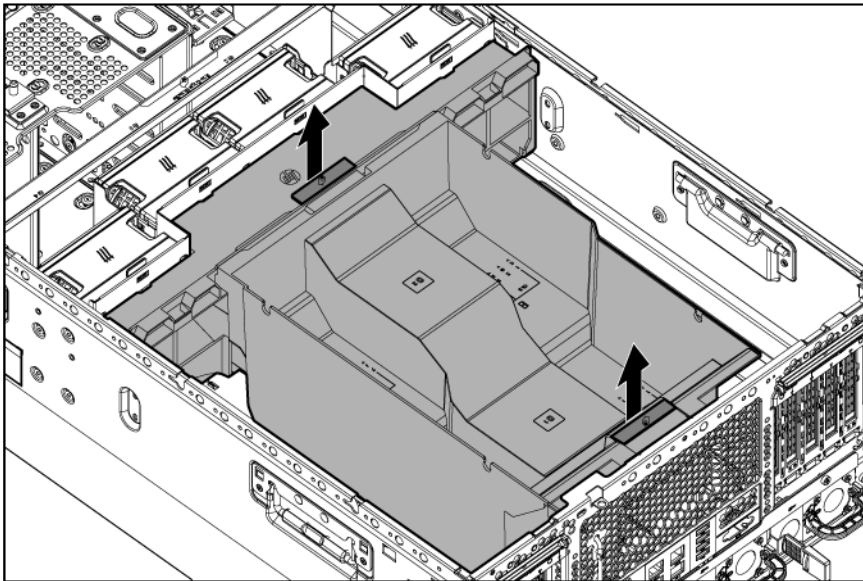
If the locking latch is locked, use a T-15 Torx screwdriver to unlock it.

To replace the component, reverse the removal procedure.

Air baffle

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 29).
6. Remove the air baffle.



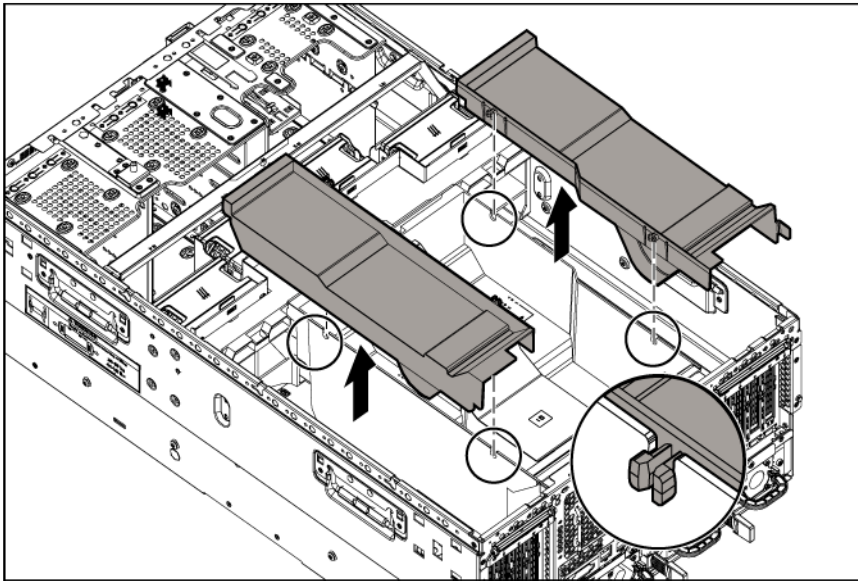
To replace the component, reverse the removal procedure.

PCI air baffles

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).

3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 29).
6. Remove the PCI air baffles.



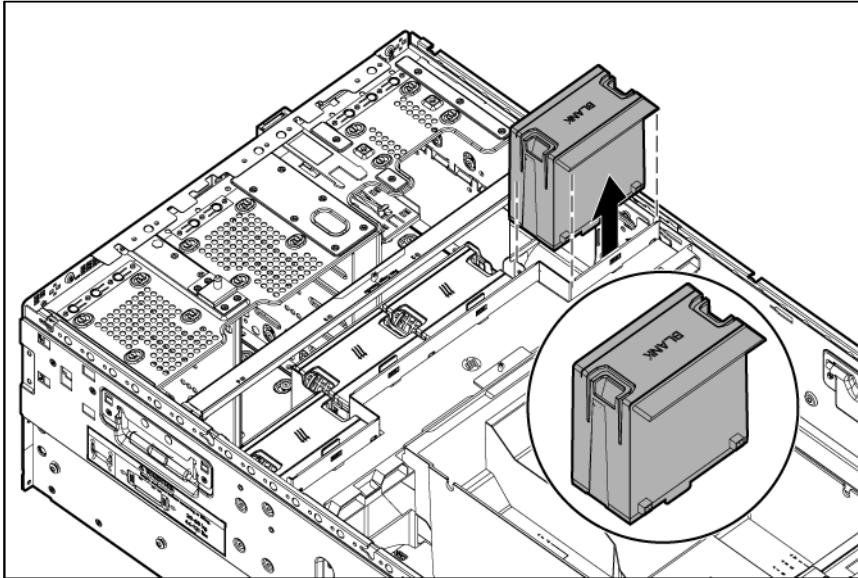
To replace the component, reverse the removal procedure.

Fan blank

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 29).

6. Remove the fan blank.



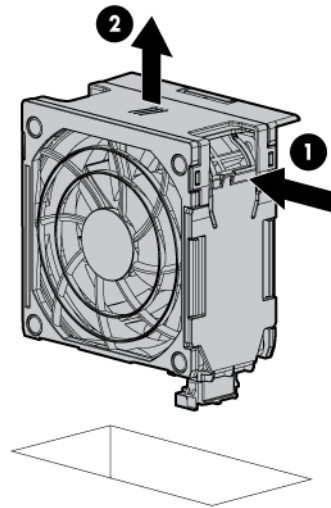
To replace the component, reverse the removal procedure.

Fan

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 29).

6. Remove the fan.



To replace the component, reverse the removal procedure.

Fan cage

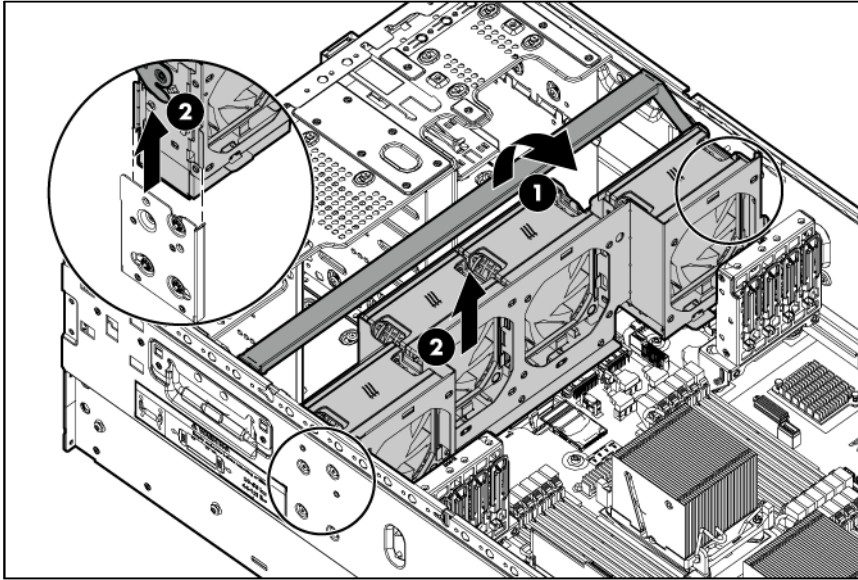


IMPORTANT: When installing or replacing server components, one or more fans might need to be removed. To prevent an orderly or immediate server shutdown, HP highly recommends powering down the server during these procedures. To determine if powering down is required, see the specific procedure.

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page [27](#)).
 - o For rack models, if installed, remove the security bezel (on page [27](#)).
2. Power down the server (on page [26](#)).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page [28](#)).
5. Remove the access panel ("[Access panel](#)" on page [29](#)).
6. Remove the air baffle ("[Air baffle](#)" on page [30](#)).

7. Remove the fan cage.



To replace the component, reverse the removal procedure.

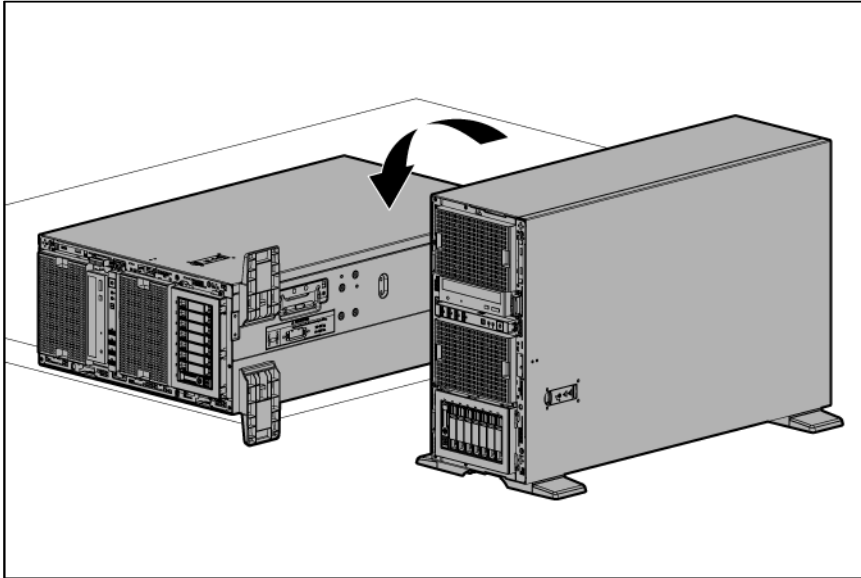
Tower feet

NOTE: This procedure applies to tower servers only.

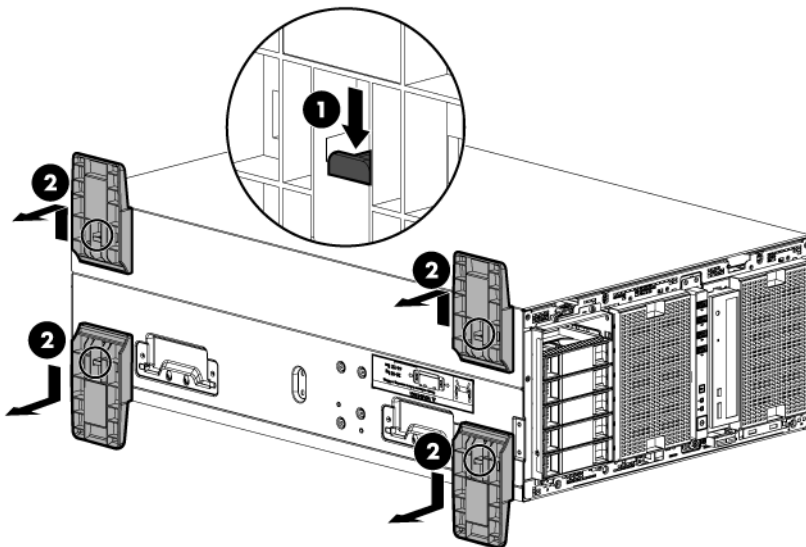
To remove the component:

1. Open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.

4. Place the server on the side.



5. Remove the tower feet.



To replace the component, reverse the removal procedure.

Component box blank

To remove the component:

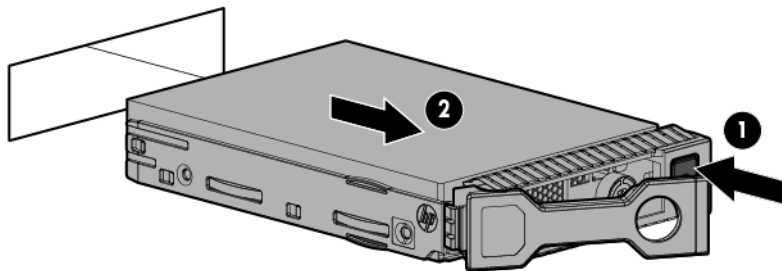
1. For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
2. For rack models, do the following:
 - a. If installed, remove the security bezel (on page 27).
 - b. Power down the server (on page 26).
 - c. Remove all power:
 - i. Disconnect each power cord from the power source.



WARNING: To reduce the risk of injury from electric shock, do not remove more than one drive carrier at a time.

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Remove the drive.



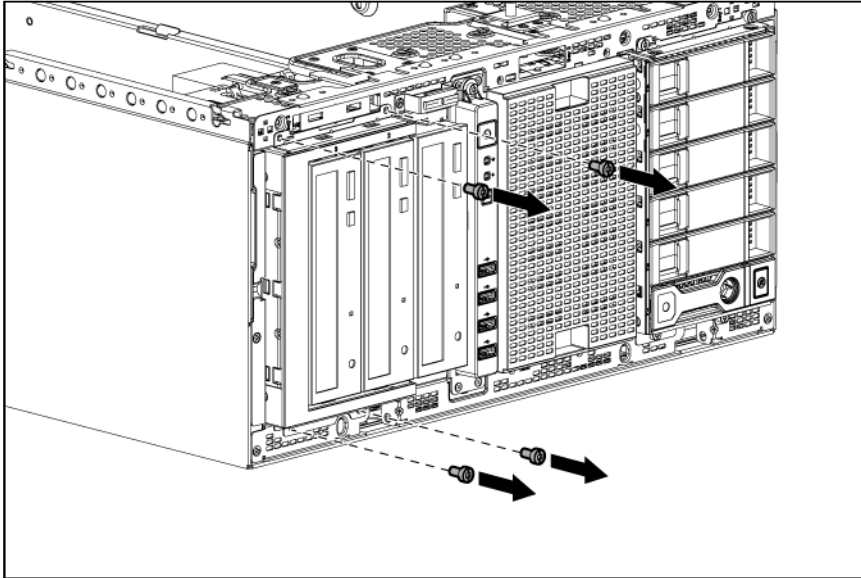
To replace the component, reverse the removal procedure.

Optical drive cage

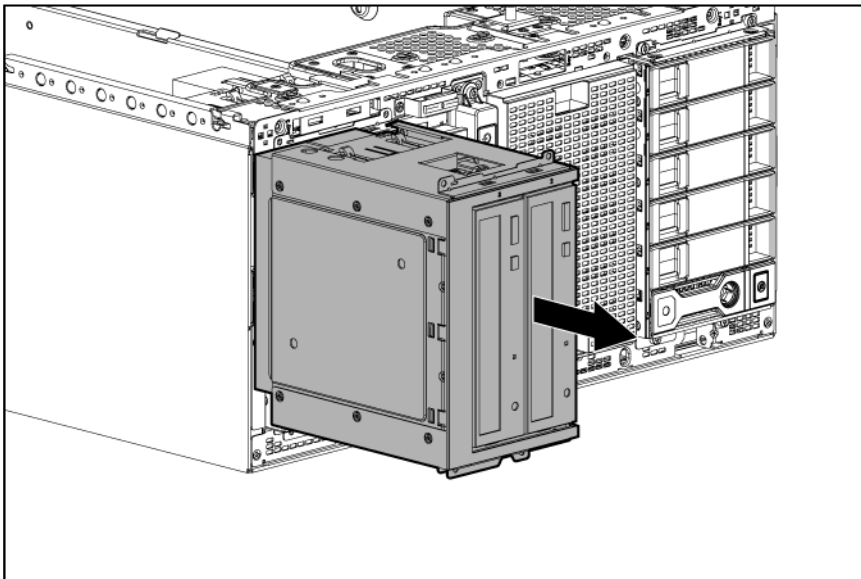
To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.
 - b. Remove the access panel ("[Access panel](#)" on page 29).
5. For rack models, do the following:
 - a. Extend the server from the rack (on page 28).
 - b. Remove the access panel ("[Access panel](#)" on page 29).
 - o Release thumbscrews and remove the rack bezel.
6. Remove the air baffle ("[Air baffle](#)" on page 30).
7. Remove the fan cage.
8. Disconnect the data cable and the power cable from the rear of the optical drive cage.

- Using the T-15 screwdriver, loosen T-15 screws securing the optical drive cage.



- Remove the optical drive cage.



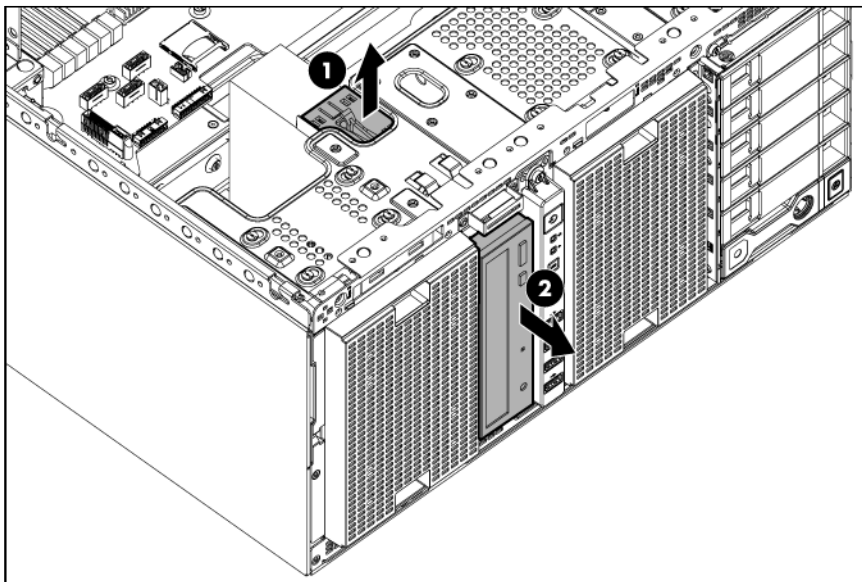
To replace the component, reverse the removal procedure.

Optical drive

To remove the component:

- Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page [27](#)).
 - For rack models, if installed, remove the security bezel (on page [27](#)).
- Power down the server (on page [26](#)).
- Remove all power:
 - Disconnect each power cord from the power source.

- b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.
 - b. Remove the access panel ("[Access panel](#)" on page 29).
5. For rack models, do the following:
 - a. Extend the server from the rack (on page 28).
 - b. Remove the access panel ("[Access panel](#)" on page 29).
 - c. Release thumbscrews and remove the rack bezel.
6. Remove the air baffle ("[Air baffle](#)" on page 30).
7. Remove the fan cage.
8. Disconnect and remove the optical drive power and data cables.
9. Remove the optical drive.



To replace the component, reverse the removal procedure.

Front I/O assembly

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.

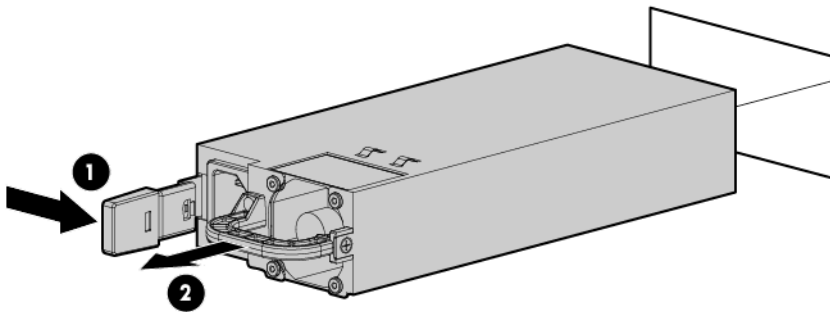
Power supply module

- ⚠ CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

To remove the component:

1. Do one of the following:
 - For tower models, open and remove the bezel ("Remove the tower bezel" on page 27).
 - For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Access the product rear panel.
5. If removing a DC power supply, first remove the grounding wire.
6. Remove the power supply.

- ⚠ WARNING:** To reduce the risk of personal injury from hot surfaces, allow the power supply or power supply blank to cool before touching it.



To replace the component, reverse the removal procedure.

Power supply backplane

- ⚠ CAUTION:** To prevent improper cooling and thermal damage, do not operate the server unless all bays are populated with either a component or a blank.

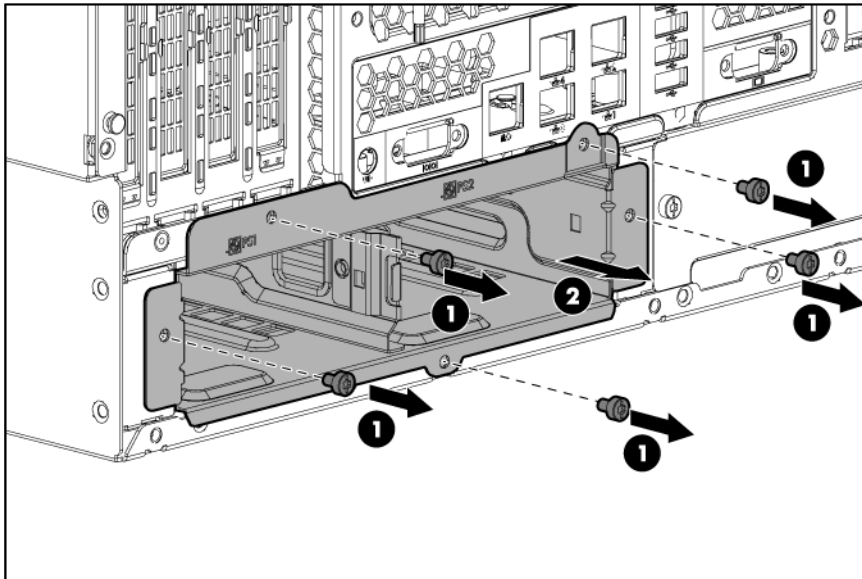
To remove the component:

1. Do one of the following:
 - For tower models, open and remove the bezel ("Remove the tower bezel" on page 27).
 - For rack models, if installed, remove the security bezel (on page 27).

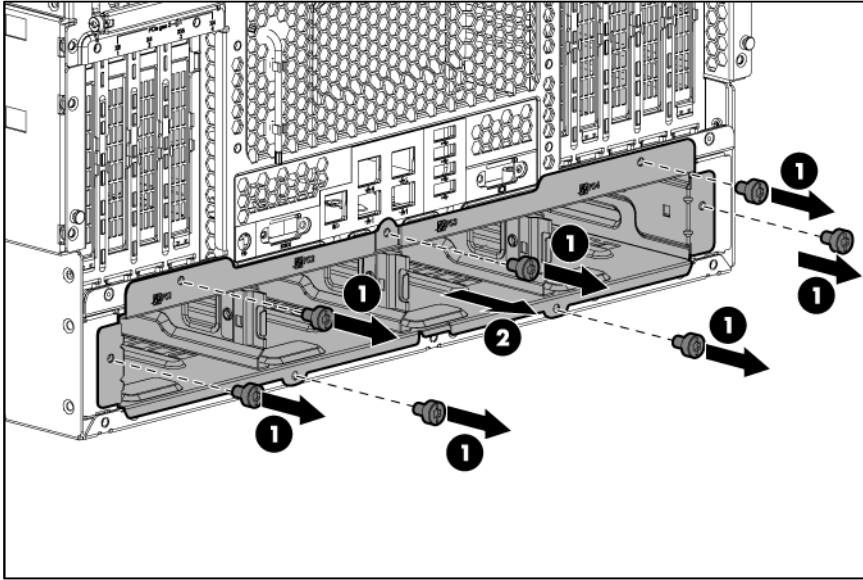
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Access the product rear panel.
6. Remove all power supply modules from the power supply cage ("Power supply module" on page 41).

⚠ WARNING: To reduce the risk of personal injury from hot surfaces, allow the power supply or power supply blank to cool before touching it.

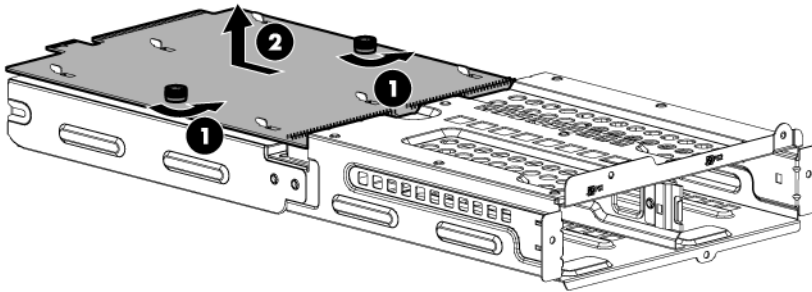
7. Remove the screws, and slide the power supply cage out of the server:
 - o Two-bay power supply configuration



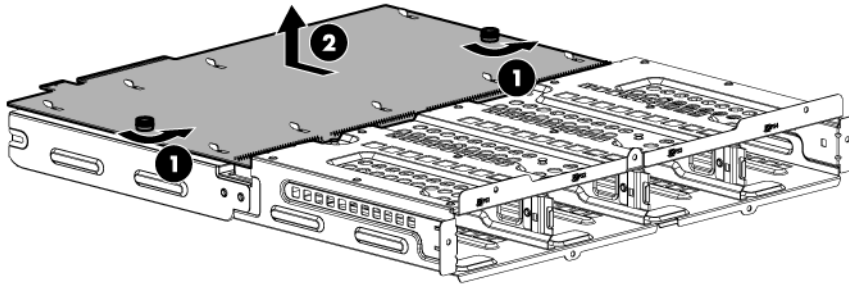
- Four-bay power supply configuration



8. Loosen the two thumbscrews, and remove the power supply backplane from the cage:
- Two-bay power supply backplane board



- Four-bay power supply backplane board

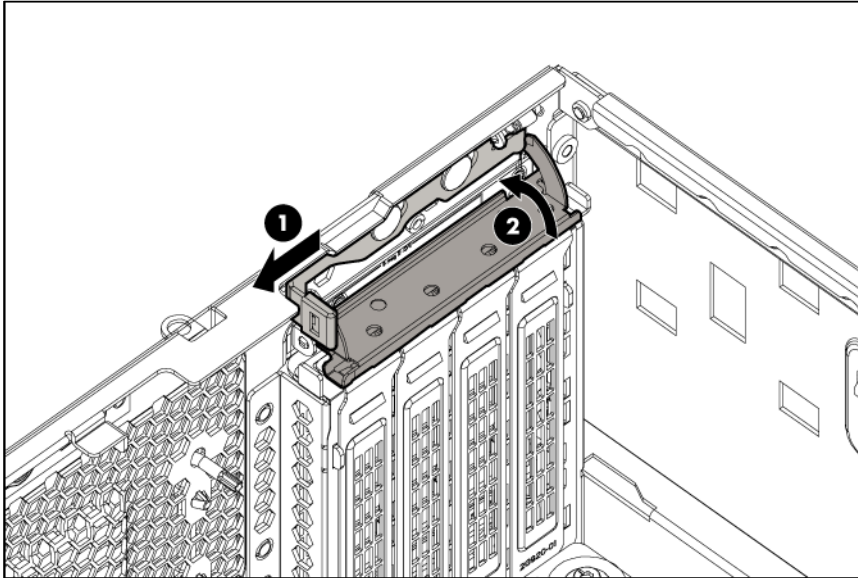


To replace the component, reverse the removal procedure, if the screws are not attached to the backplane assembly, use the screws provided in the spare backplane assembly kit.

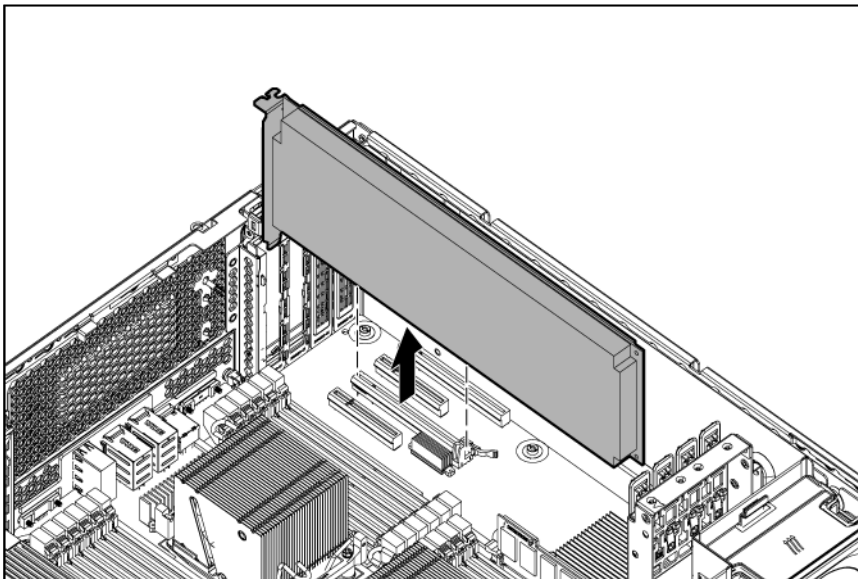
Expansion board

1. Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page [27](#)).
 - For rack models, if installed, remove the security bezel (on page [27](#)).
2. Power down the server (on page [26](#)).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - For tower models, place the server on a flat, level surface with the access panel facing up.
 - For rack models, extend the server from the rack (on page [28](#)).
5. Remove the access panel ("[Access panel](#)" on page [29](#)).
6. Remove the air baffle ("[Air baffle](#)" on page [30](#)).

7. Open the PCI retainer latch.



8. Remove the expansion board.



NOTE: If removing an expansion board from slots 3, 6 or 8, first release the retaining lever on the system board and then remove the card from the system.

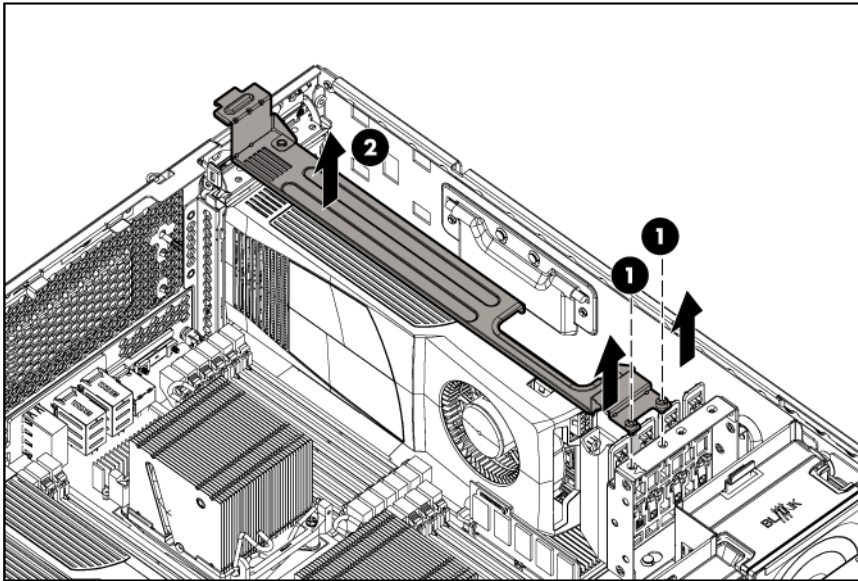
To replace the component, reverse the removal procedure.

Graphic card adapter

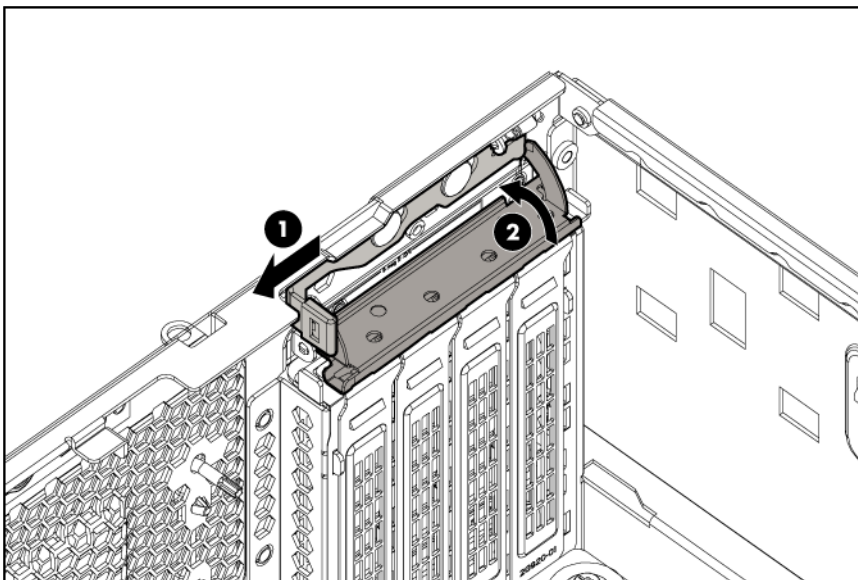
To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).

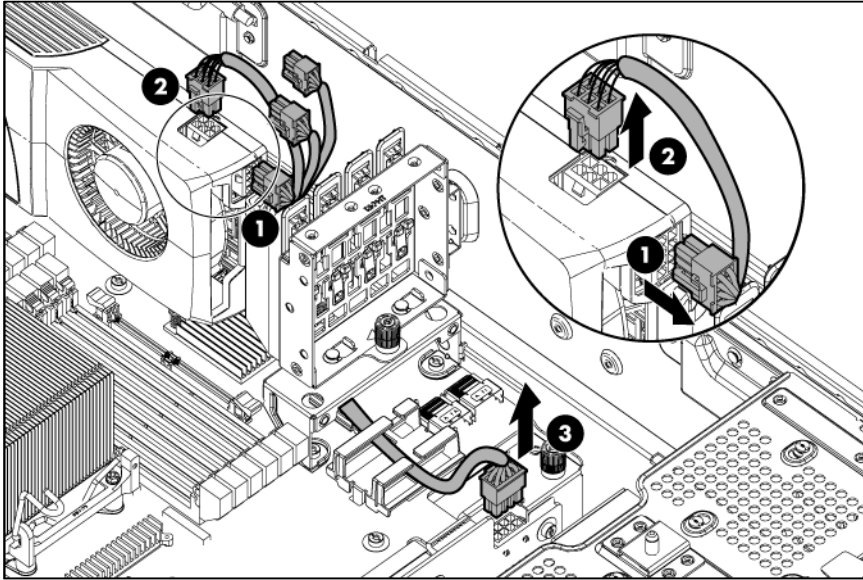
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("Access panel" on page 29).
6. Remove the air baffle ("Air baffle" on page 30).
7. Loosen the screws, and then remove the graphic card bracket.



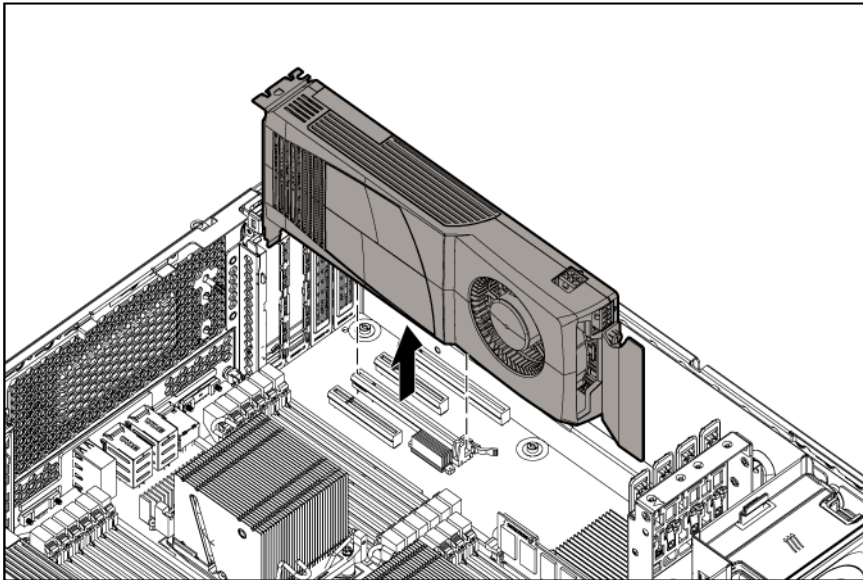
8. Open the PCI retainer latch.



9. Disconnect the cables from the graphic card.



10. Remove the graphic card.



To replace the component, reverse the removal procedure.

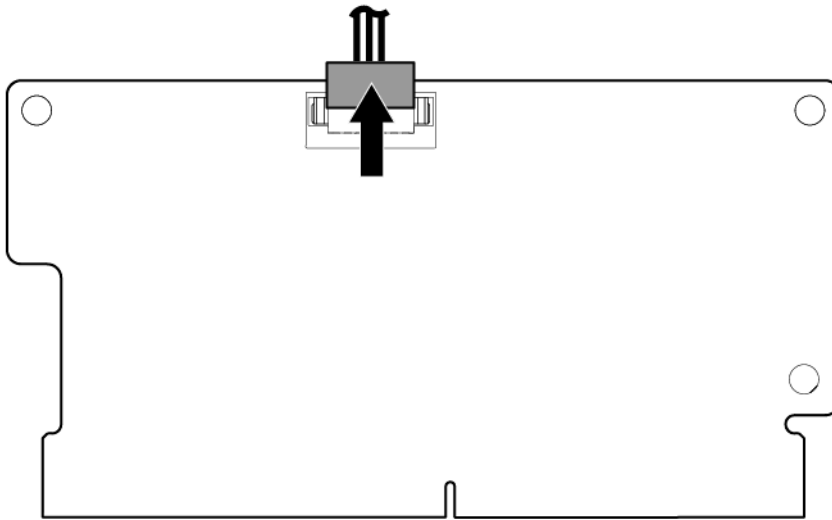
Cache module

- CAUTION:** In systems that use external data storage, be sure that the server is the first unit to be powered down and the last to be powered back up. Taking this precaution ensures that the system does not erroneously mark the drives as failed when the server is powered up.

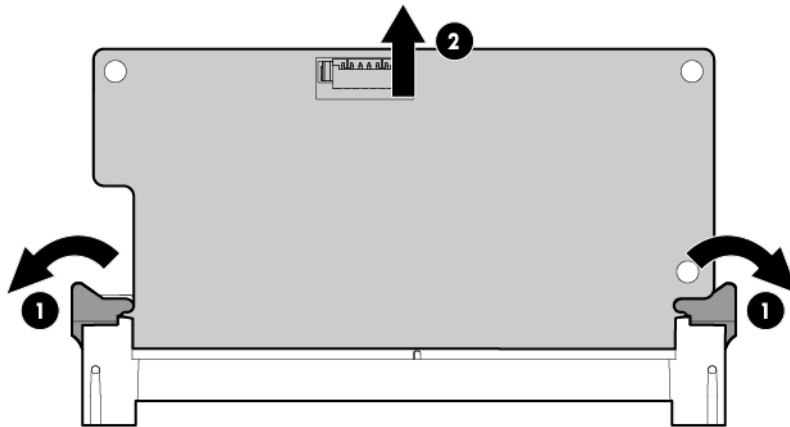
To remove the component:

1. Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - For rack models, if installed, remove the security bezel (on page 27).

2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("Access panel" on page 29).
6. Remove the air baffle ("Air baffle" on page 30).
7. Disconnect the capacitor pack cable from the cache module.



8. Remove the cache module.



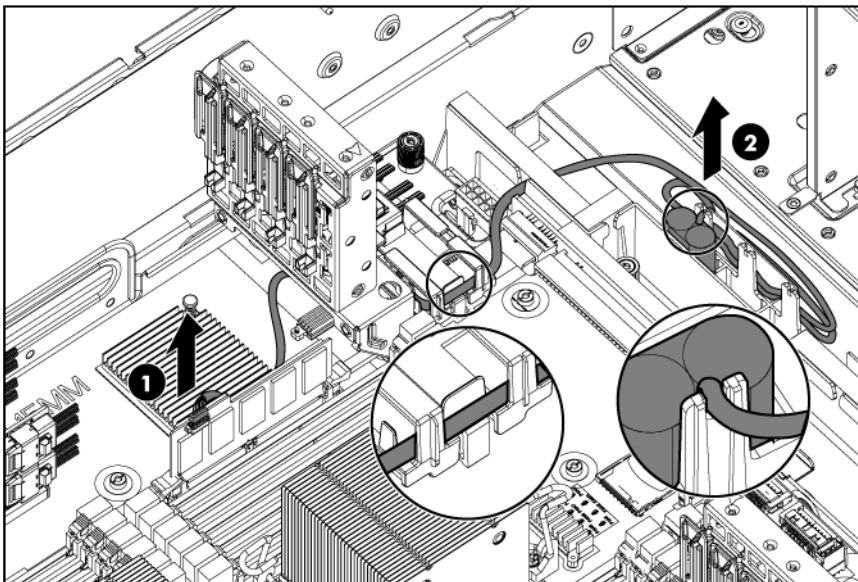
To replace the component, reverse the removal procedure.

FBWC capacitor pack

-
- △ **CAUTION:** To prevent a server malfunction or damage to the equipment, do not add or remove the battery pack while an array capacity expansion, RAID level migration, or stripe size migration is in progress.
-
- △ **CAUTION:** After the server is powered down, wait for 30 seconds and then check the amber LED before disconnecting the cable from the cache module. If the amber LED flashes after 30 seconds, do not disconnect the cable from the cache module. The cache module is backing up data, and data will be lost if the cable is disconnected while the amber LED is still flashing.
-

To remove the component:

1. Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - For tower models, place the server on a flat, level surface with the access panel facing up.
 - For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 29).
6. Remove the air baffle ("[Air baffle](#)" on page 30).
7. Remove the fan cage.
8. Disconnect the cable from the cache module only if the capacitor pack is not being used to recover data from the server or transfer data to another server.
9. Remove the capacitor pack.

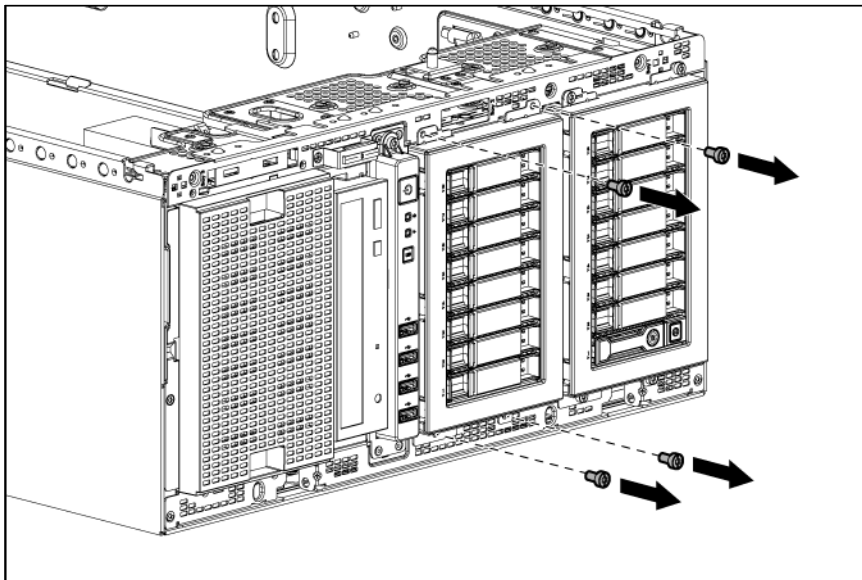


To replace the component, reverse the removal procedure.

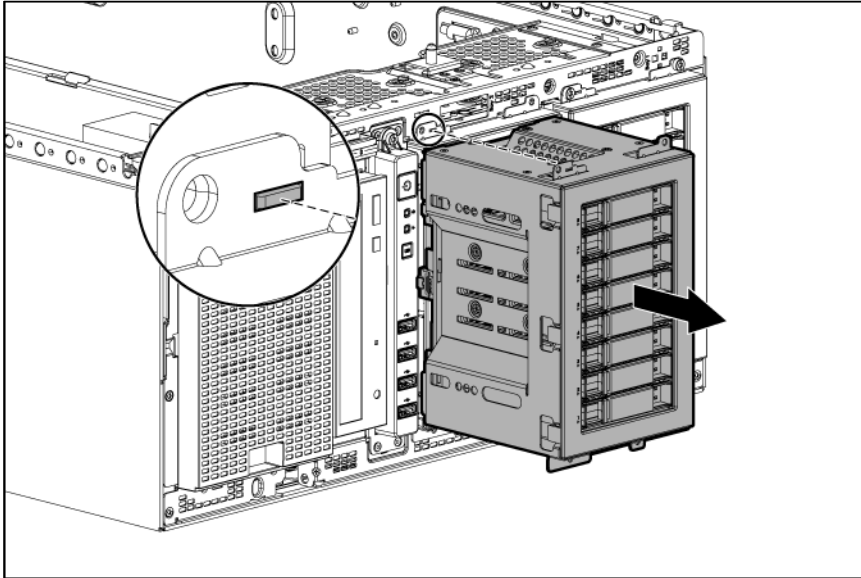
SFF drive backplane

To remove the component:

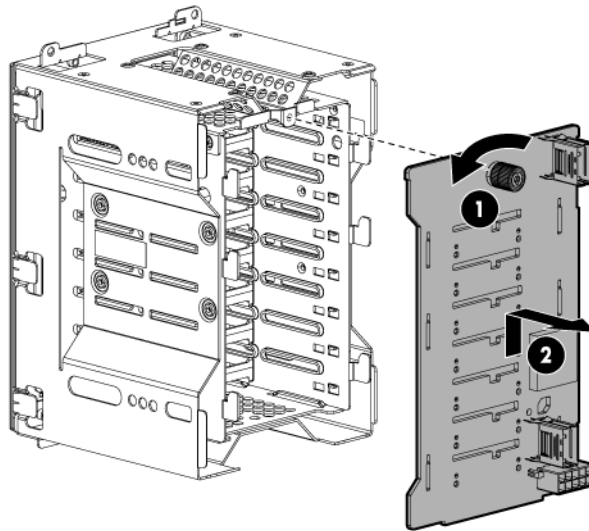
1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.
 - b. Remove the access panel ("[Access panel](#)" on page 29).
5. For rack models, do the following:
 - a. Extend the server from the rack (on page 28).
 - b. Remove the access panel ("[Access panel](#)" on page 29).
 - c. Release thumbscrews and remove the rack bezel.
6. Disconnect all cables from the drive backplane.
7. Using a T-15 screwdriver, remove the screws that secure the SFF drive cage to the server.



8. Remove the SFF drive cage.



9. Remove all drives from the drive cage ("Drive" on page 36).
10. Loosen the thumbscrew on the drive backplane and remove it from the cage.



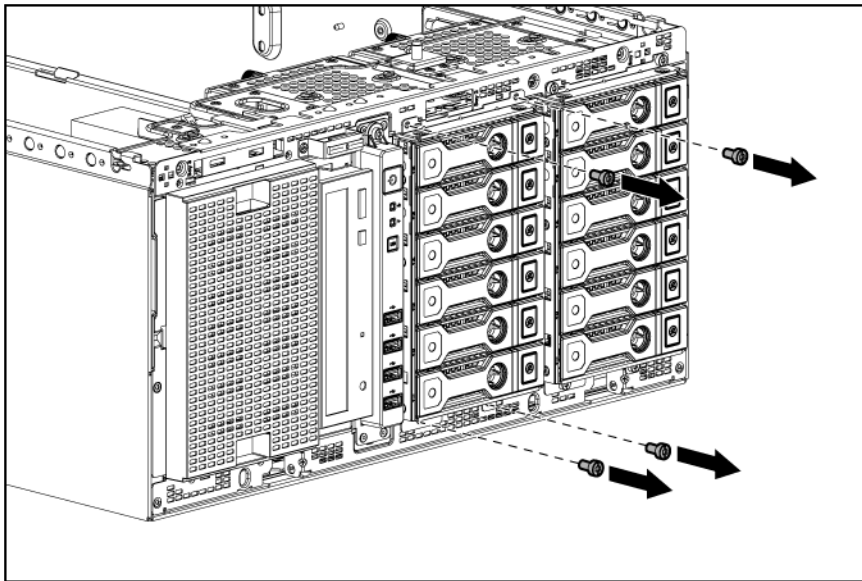
To replace the component, reverse the removal procedure.

LFF drive backplane

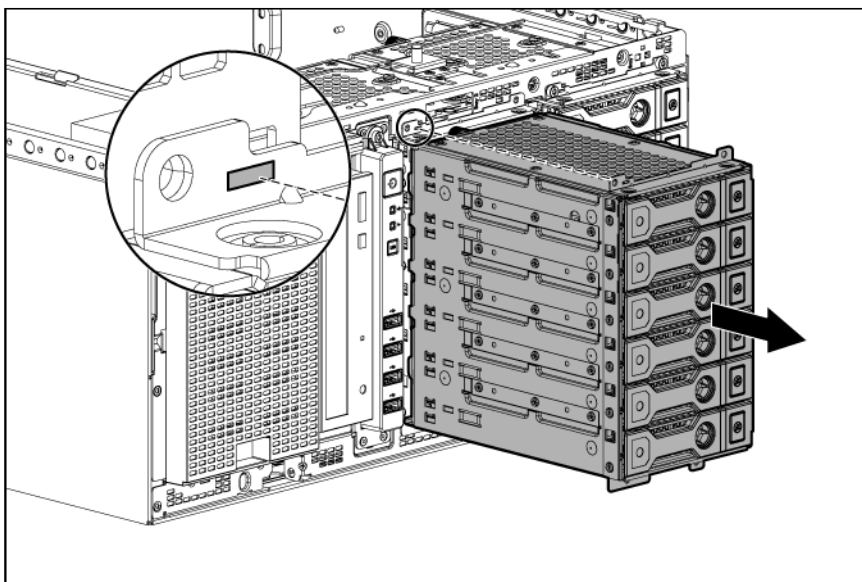
To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("Remove the tower bezel" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:

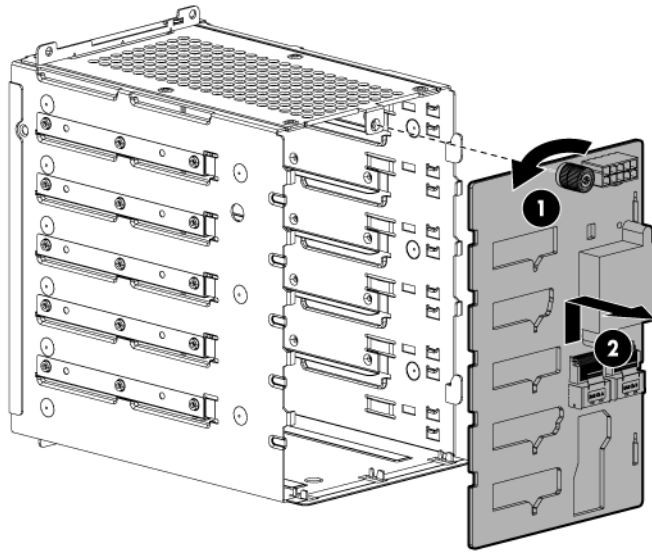
- a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.
 - b. Remove the access panel ("[Access panel](#)" on page 29).
5. For rack models, do the following:
 - a. Extend the server from the rack (on page 28).
 - b. Remove the access panel ("[Access panel](#)" on page 29).
 - c. Release thumbscrews and remove the rack bezel.
6. Disconnect all cables from the drive backplane.
7. Using a T-15 screwdriver, remove the screws that secure the LFF drive cage to the server.



8. Remove the LFF drive cage.



9. Remove all drives from the drive cage ("Drive" on page 36).
10. Loosen the thumbscrew on the drive backplane and remove it from the cage.



To replace the component, reverse the removal procedure.

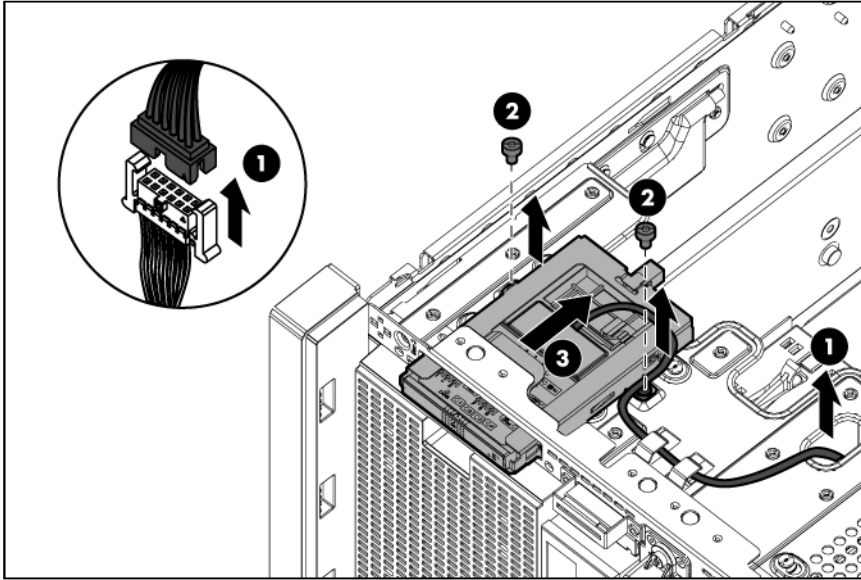
Systems Insight Display assembly

CAUTION: When routing cables, always be sure that the cables are not in a position where they can be pinched or crimped.

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("Remove the tower bezel" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.
 - b. Remove the access panel ("Access panel" on page 29).
5. For rack models, do the following:
 - a. Extend the server from the rack (on page 28).
 - b. Remove the access panel ("Access panel" on page 29).
 - c. Release thumbscrews and remove the rack bezel.
6. Disconnect the cable that connects the Systems Insight Display assembly to the system board.
7. Remove the thumbscrews securing the Systems Insight Display assembly.

8. Remove the Systems Insight Display assembly.



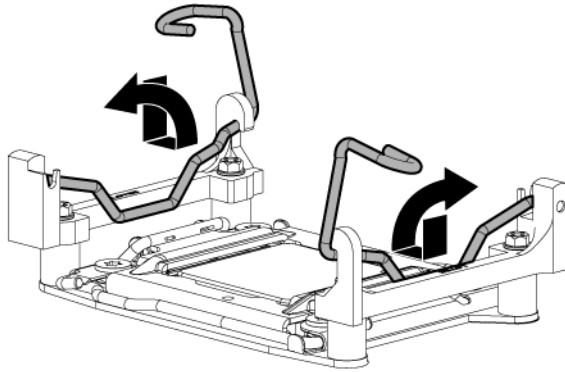
To replace the component, reverse the removal procedure.

Heatsink

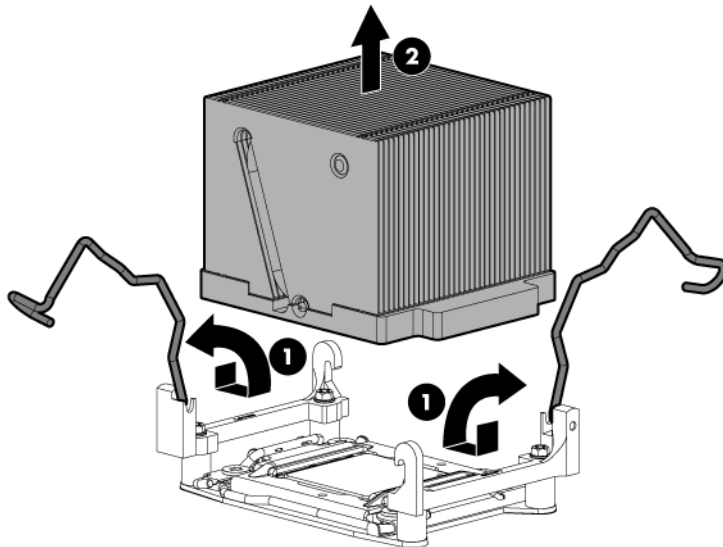
To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("[Access panel](#)" on page 29).
6. Remove the air baffle ("[Air baffle](#)" on page 30).

7. Open the heatsink retaining levers.



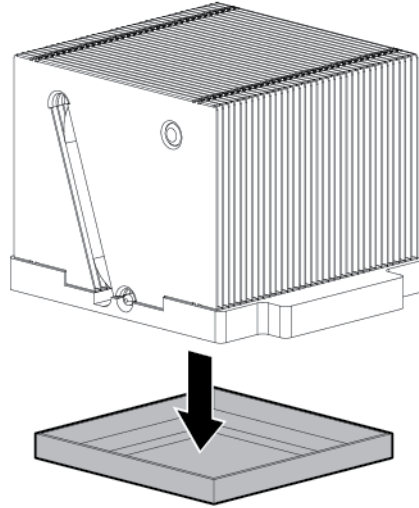
8. Remove the heatsink.



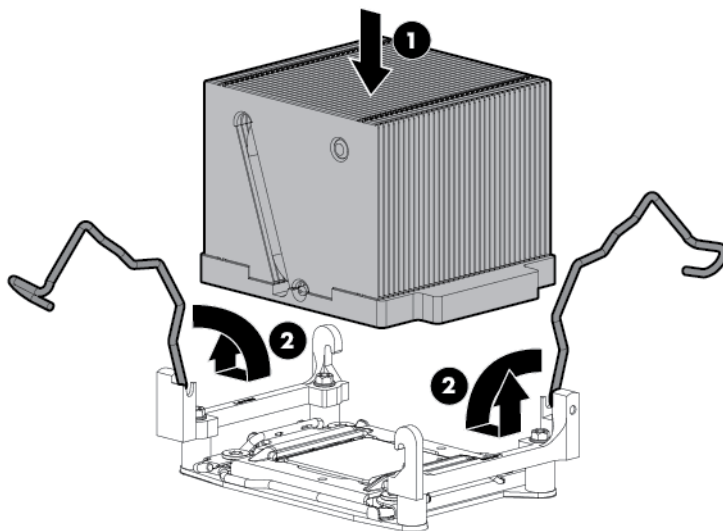
To replace the heatsink:

1. Use the alcohol swab to remove all the existing thermal grease from the processor. Allow the alcohol to evaporate before continuing.

2. Remove the heatsink protective cover.



3. Install the heatsink, and then close the heatsink retaining levers.



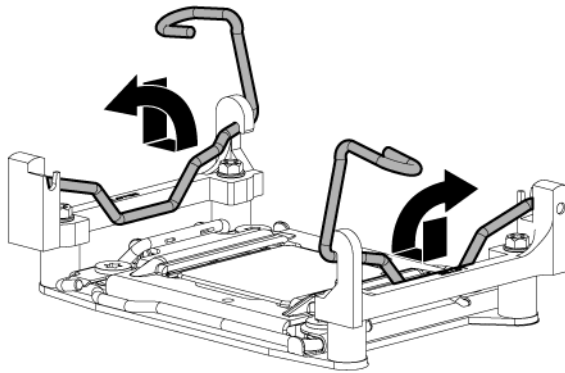
4. Install the air baffle.
5. Install the access panel.
6. Do one of the following:
 - o For tower models, return the server to an upright position, and then install the bezel.
 - o For rack models, slide the server back into the rack.
7. Connect each power cord to the server.
8. Connect each power cord to the power source.
9. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

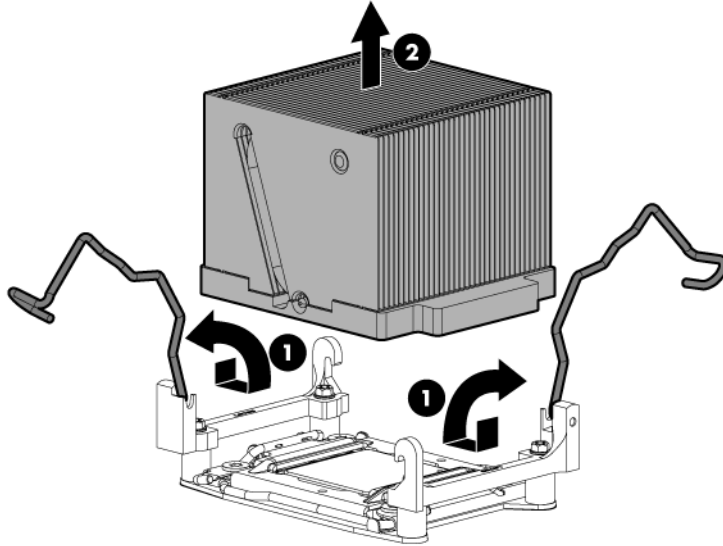
Heatsink Retaining Levers

To remove the component:

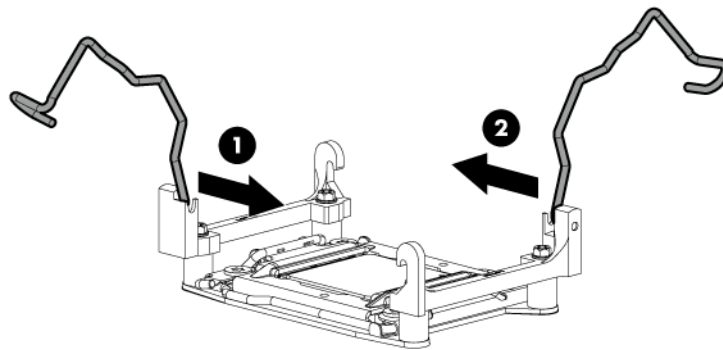
1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page [27](#)).
 - o For rack models, if installed, remove the security bezel (on page [27](#)).
2. Power down the server (on page [26](#)).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page [28](#)).
5. Remove the access panel ("[Access panel](#)" on page [29](#)).
6. Remove the air baffle ("[Air baffle](#)" on page [30](#)).
7. Open the heatsink retaining levers.



8. Remove the heatsink.



9. Remove the heatsink retaining levers.



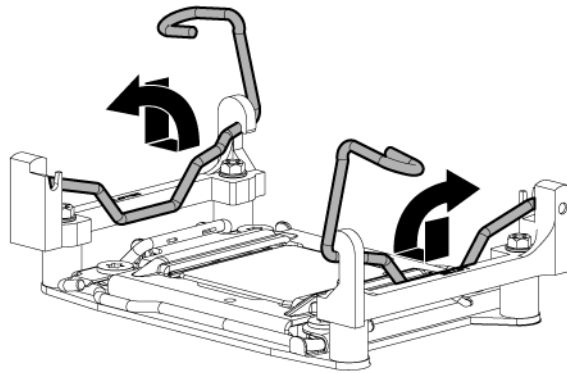
To replace the component, reverse the removal procedure.

Processor

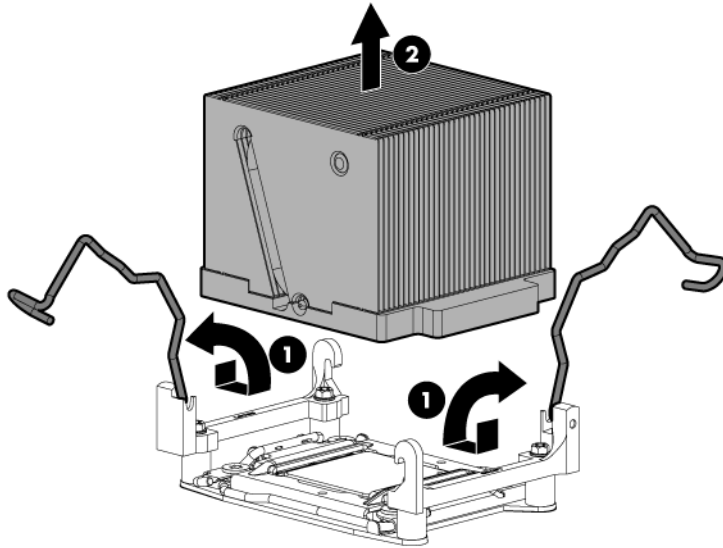
-
- WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.
-
- CAUTION:** To prevent possible server malfunction and damage to the equipment, multiprocessor configurations must contain processors with the same part number.
-
- CAUTION:** The heatsink thermal interface media is not reusable and must be replaced if the heatsink is removed from the processor after it has been installed.
-
- CAUTION:** To prevent possible server overheating, always populate processor socket 2 with a processor and a heatsink or a processor socket cover and a heatsink blank.
-
- IMPORTANT:** Processor socket 1 must be populated at all times or the server does not function.
-

To remove the component:

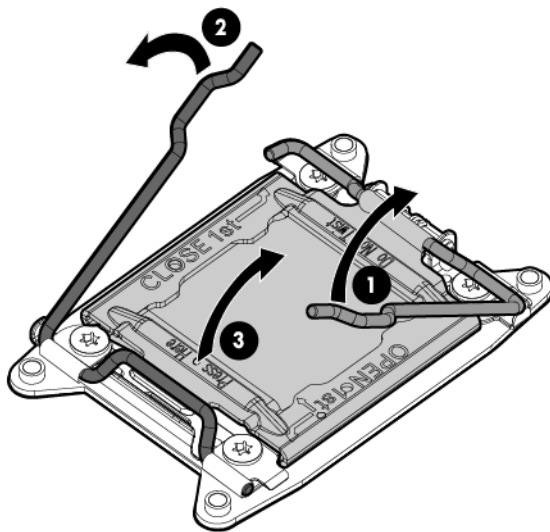
1. Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page [27](#)).
 - For rack models, if installed, remove the security bezel (on page [27](#)).
2. Power down the server (on page [26](#)).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - For tower models, place the server on a flat, level surface with the access panel facing up.
 - For rack models, extend the server from the rack (on page [28](#)).
5. Remove the access panel ("[Access panel](#)" on page [29](#)).
6. Remove the air baffle ("[Air baffle](#)" on page [30](#)).
7. Open the heatsink retaining levers.



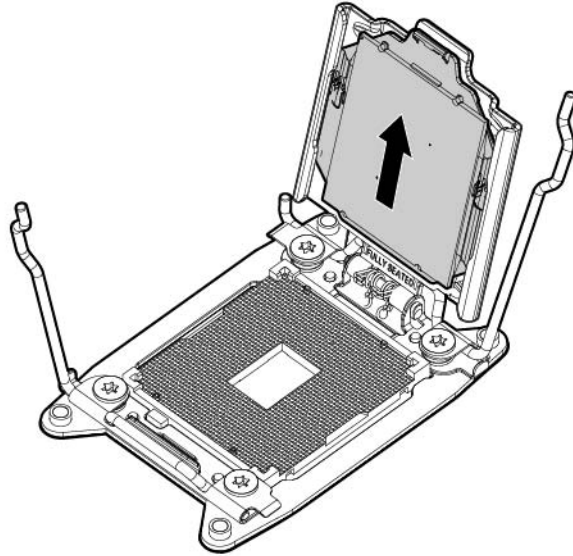
8. Remove the heatsink.



9. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



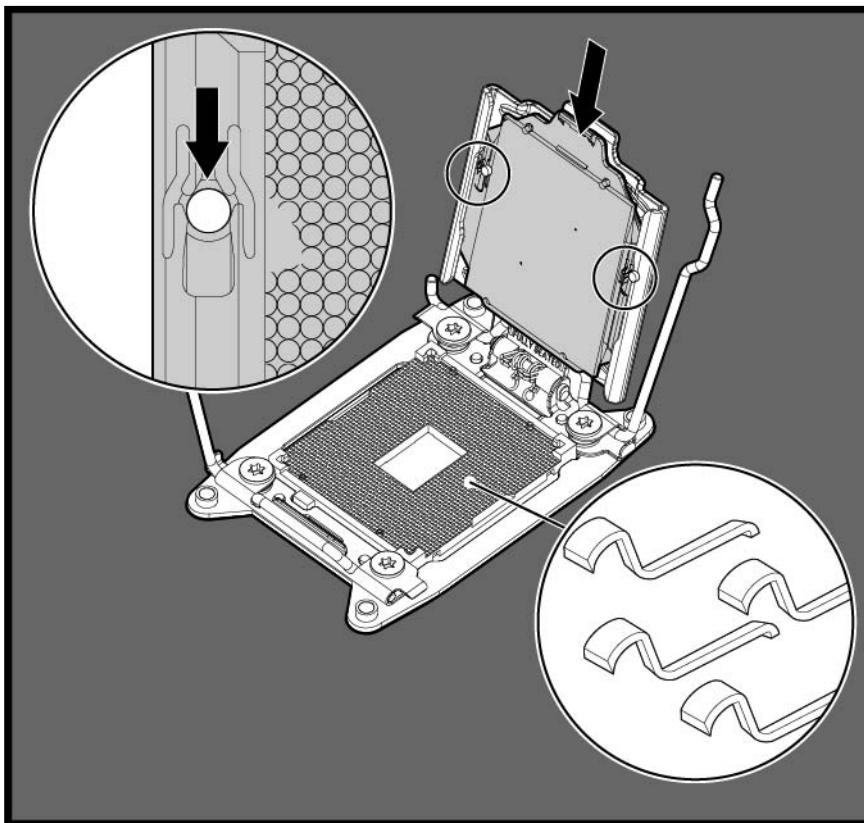
10. Remove the processor from the processor retaining bracket.



CAUTION: To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.

To install a processor:

1. Install the processor. Verify that the processor is fully seated in the processor retaining bracket by visually inspecting the processor installation guides on either side of the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**

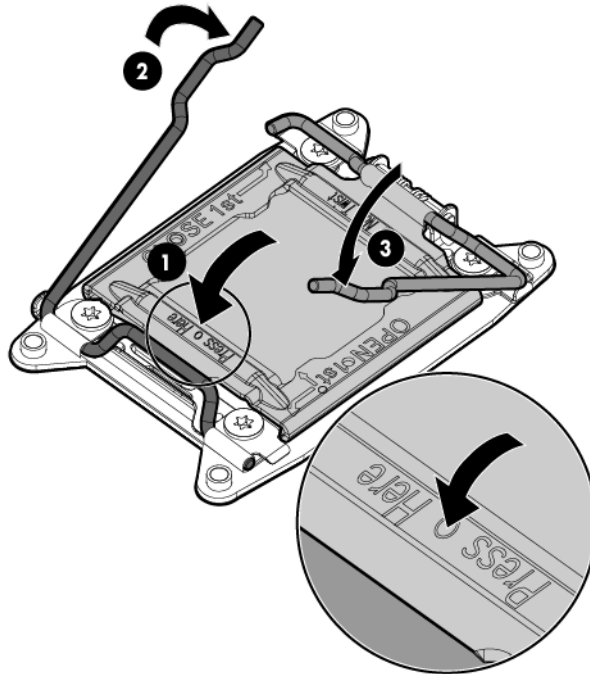


△ **CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.** To avoid damage to the system board, do not touch the processor or the processor socket contacts.

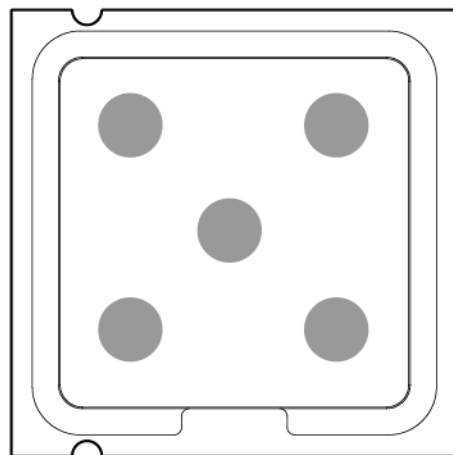
2. Close the processor retaining bracket. When the processor is installed properly inside the processor retaining bracket, the processor retaining bracket clears the flange on the front of the socket.

△ **CAUTION:** Do not press down on the processor. Pressing down on the processor may cause damage to the processor socket and the system board. Press only in the area indicated on the processor retaining bracket.

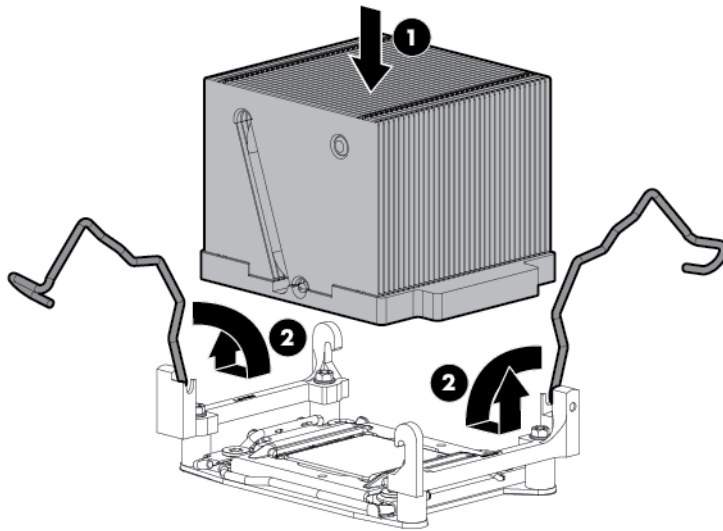
3. Press and hold the processor retaining bracket in place, and then close each processor locking lever. Press only in the area indicated on the processor retaining bracket.



4. Use the alcohol swab to remove all the existing thermal grease from the heatsink. Allow the alcohol to evaporate before continuing.
5. Apply the thermal grease to the top of the processor in the following pattern.



6. Install the heatsink, and then close the heatsink retaining levers.



7. Install the air baffle.
8. Install the access panel.
9. Do one of the following:
 - o For tower models, return the server to an upright position.
 - o For rack models, slide the server back into the rack.

10. Connect each power cord to the server.
11. Connect each power cord to the power source.
12. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

13. Do one of the following:
 - o For tower models, install the bezel.
 - o For rack models, if removed, install the security bezel.

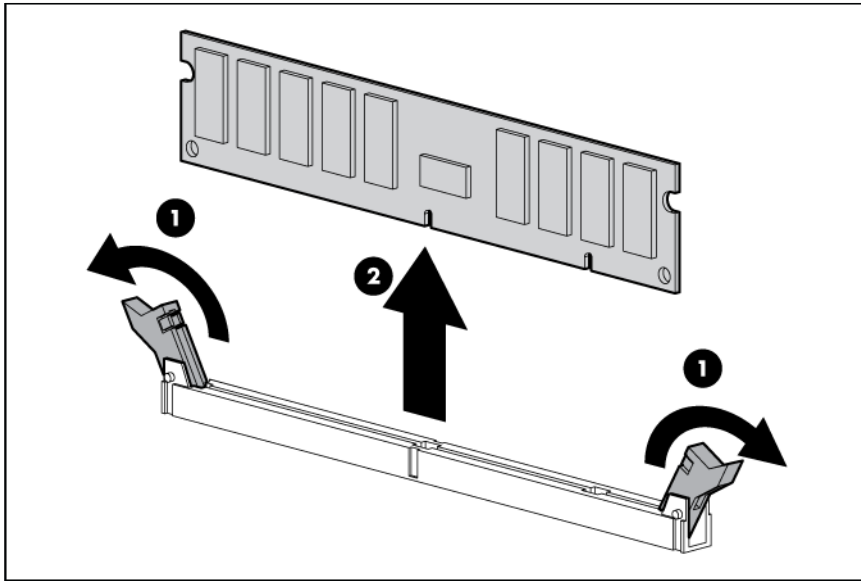
DIMMs

CAUTION: To avoid damage to the hard drives, memory, and other system components, the air baffle, drive blanks, and access panel must be installed when the server is powered up.

To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.

- b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("Access panel" on page 29).
6. Remove the air baffle ("Air baffle" on page 30).
7. Open the DIMM slot latches..
8. Remove the DIMM.



To replace the component, reverse the removal procedure.

System board

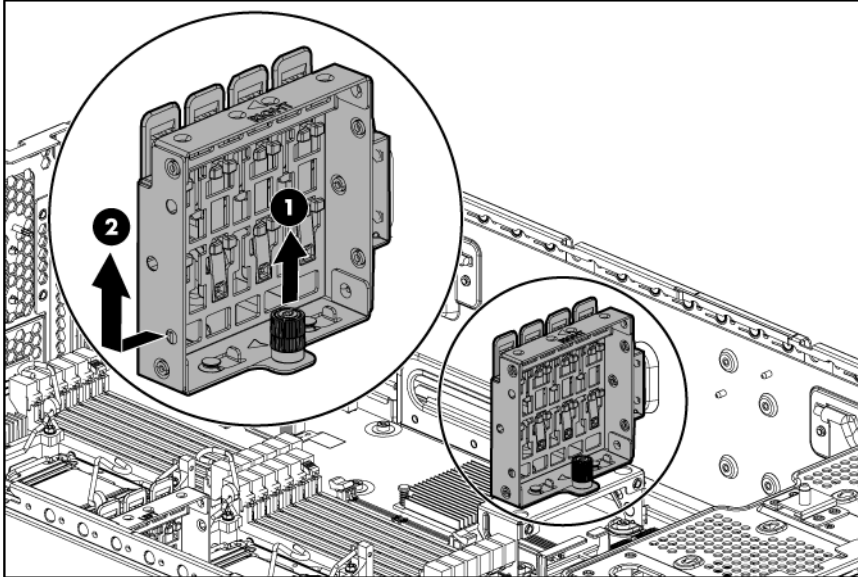


IMPORTANT: If replacing the system board or clearing NVRAM, you must re-enter the server serial number through RBSU.

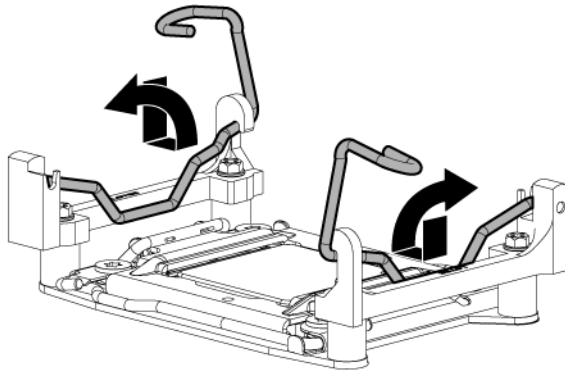
To remove the component:

1. Do one of the following:
 - o For tower models, open and remove the bezel ("Remove the tower bezel" on page 27).
 - o For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. Do one of the following:
 - o For tower models, place the server on a flat, level surface with the access panel facing up.
 - o For rack models, extend the server from the rack (on page 28).
5. Remove the access panel ("Access panel" on page 29).

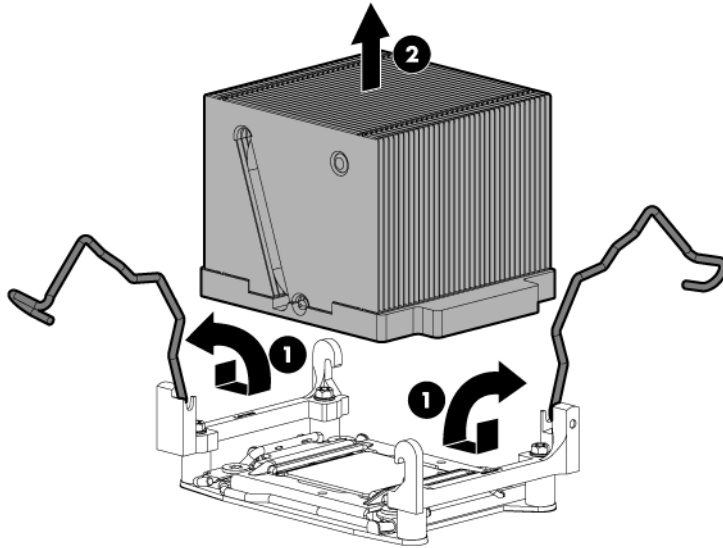
6. Remove the air baffle ("Air baffle" on page 30).
7. Remove the fan cage.
8. Remove all DIMMs ("DIMMs" on page 63).
9. Remove any installed PCI cards.
10. Remove the PCI card support bracket on both sides.



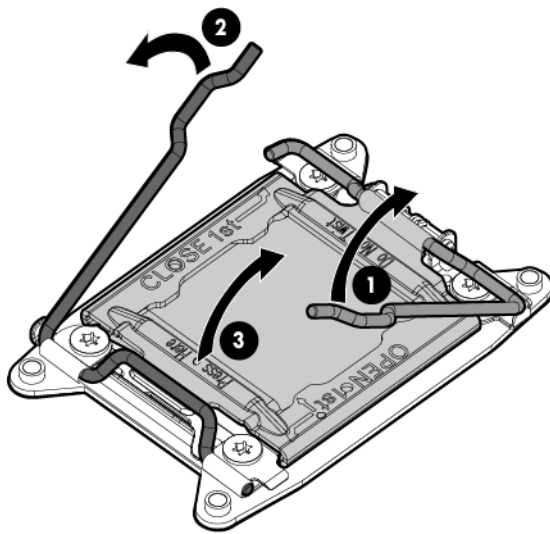
11. Disconnect all cables connected to the system board.
12. Open the heatsink retaining levers.



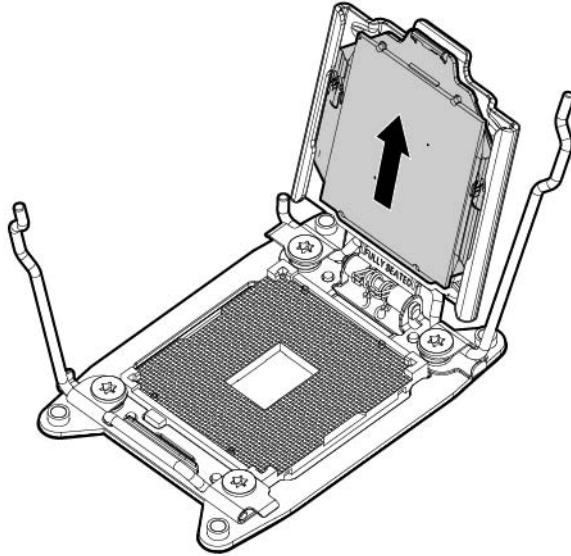
13. Remove the heatsink.



14. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.

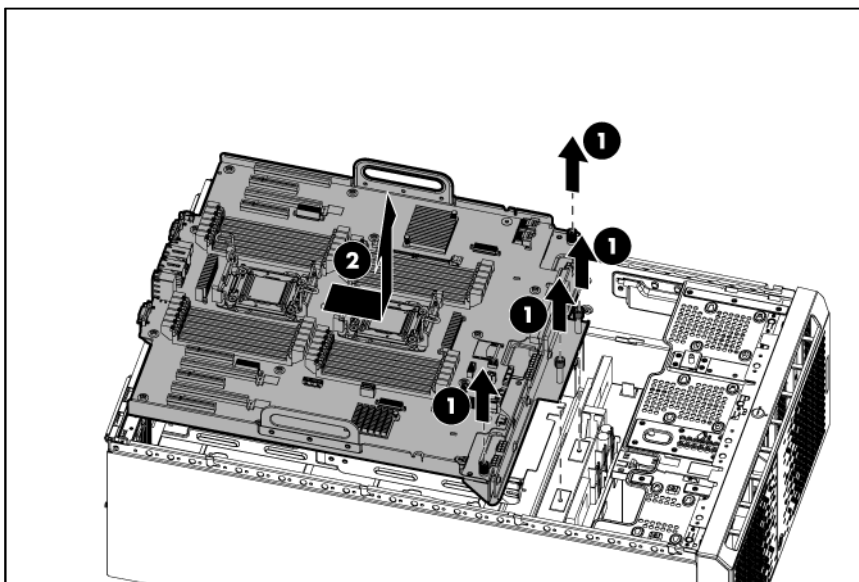


15. Remove the processor from the processor retaining bracket.



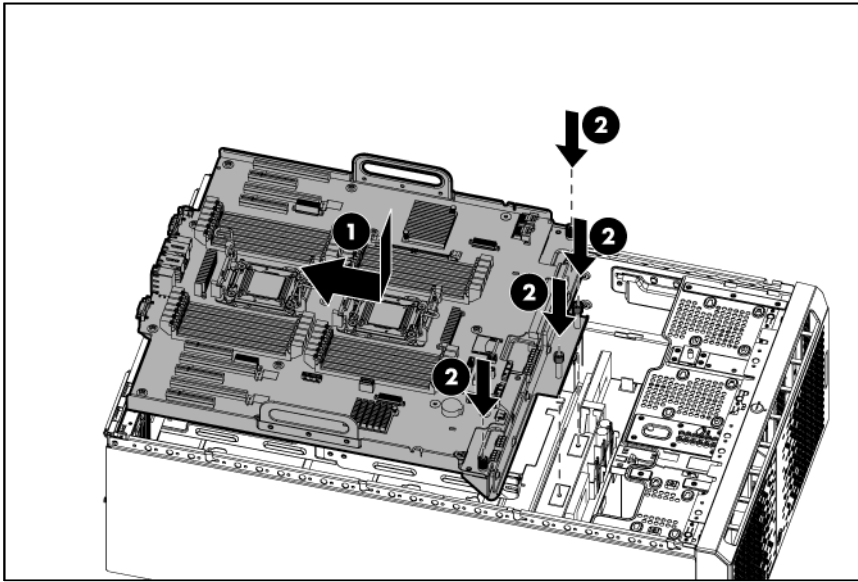
-
- △ **CAUTION:** To avoid damage to the processor, do not touch the bottom of the processor, especially the contact area.
-
- △ **CAUTION:** To avoid damage to the system board:
- Do not touch the processor socket contacts.
 - Always install the processor socket cover after removing the processor from the socket.
 - Do not tilt or slide the processor when lowering the processor into the socket.
-
- △ **CAUTION:** Removal of the processor or heatsink renders the thermal layer between the processor and heatsink useless. Clean the component with the provided alcohol swab, then add thermal grease.
-

16. Loosen the four system board thumbscrews.
17. Using the system board tray handles, slide the tray forward, and then remove the failed system board.

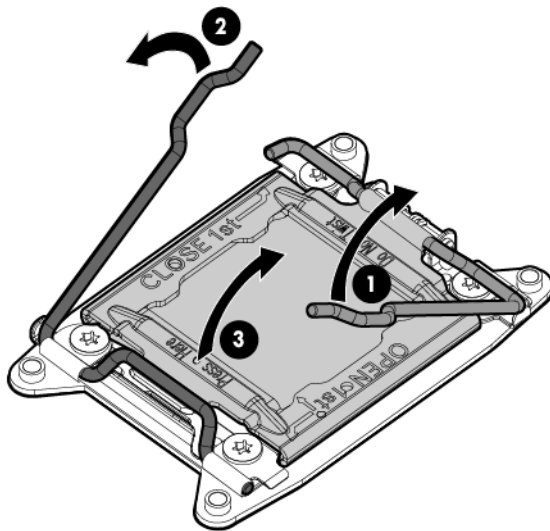


To replace the system board:

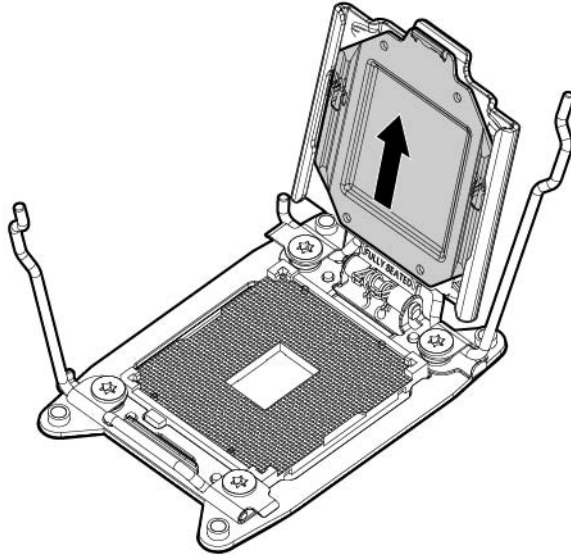
1. Install the spare system board.



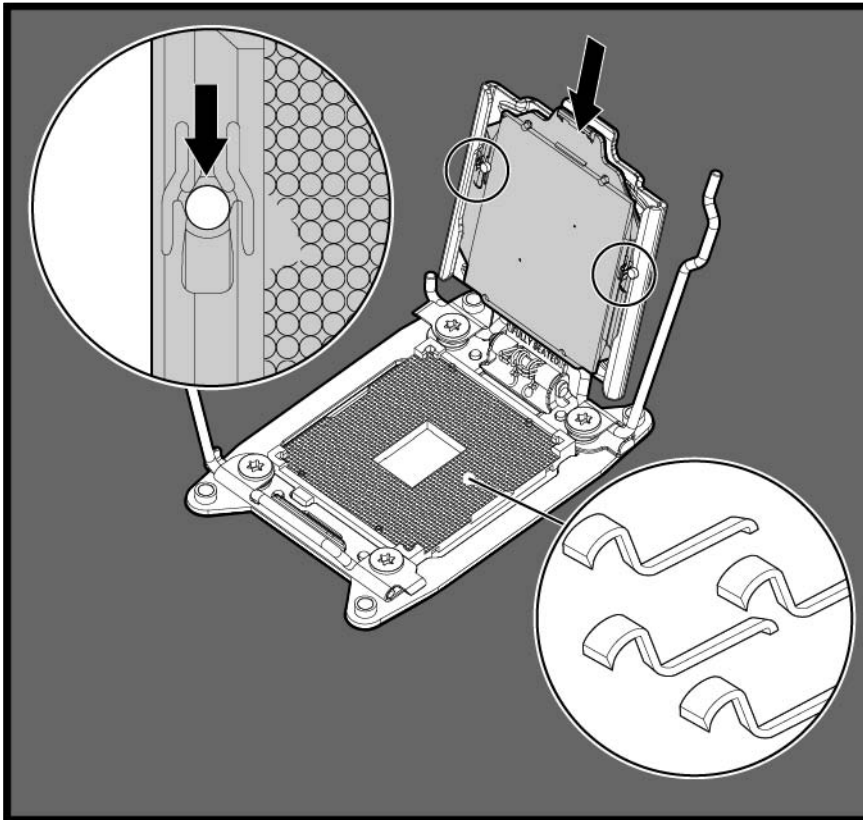
2. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



3. Remove the clear processor socket cover. Retain the processor socket cover for future use.



4. Install the processor. Verify that the processor is fully seated in the processor retaining bracket by visually inspecting the processor installation guides on either side of the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**



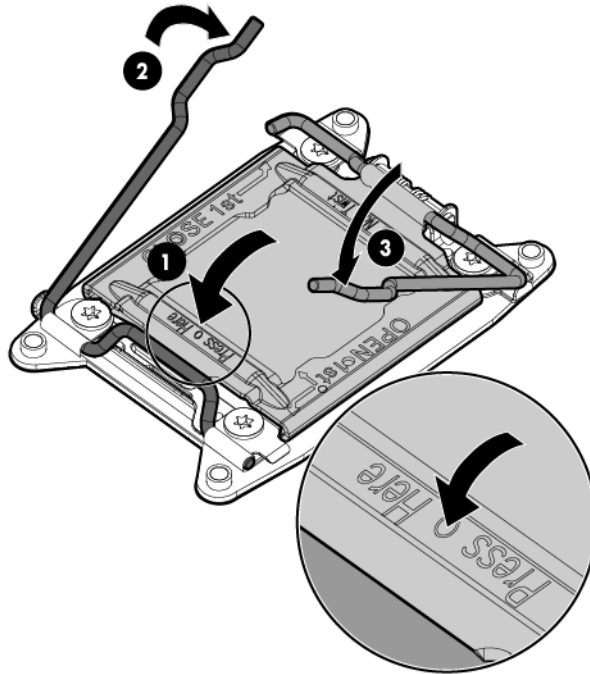
CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

5. Close the processor retaining bracket. When the processor is installed properly inside the processor retaining bracket, the processor retaining bracket clears the flange on the front of the socket.

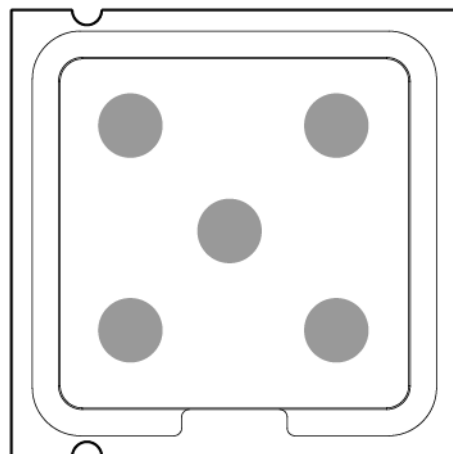


CAUTION: Do not press down on the processor. Pressing down on the processor may cause damage to the processor socket and the system board. Press only in the area indicated on the processor retaining bracket.

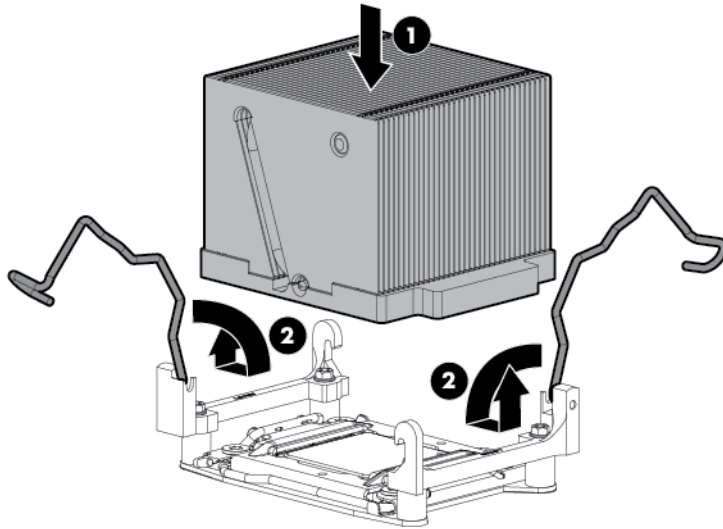
6. Press and hold the processor retaining bracket in place, and then close each processor locking lever. Press only in the area indicated on the processor retaining bracket.



7. Install the processor socket cover onto the processor socket of the failed system board.
8. Clean the old thermal grease from the heatsink and the top of the processor with the alcohol swab. Allow the alcohol to evaporate before continuing.
9. Apply all the grease to the top of the processor in the following pattern to ensure even distribution.



10. Install the heatsink, and then close the heatsink retaining levers.



11. Install the processor socket cover onto the processor socket of the failed system board.



IMPORTANT: Install all components with the same configuration that was used on the failed system board.

12. Install all components removed from the failed system board.
13. Install the access panel.
14. Do one of the following:
 - For tower models, return the server to an upright position.
 - For rack models, slide the server back into the rack.
15. Connect each power cord to the server.
16. Connect each power cord to the power source.
17. Press the Power On/Standby button.

The server exits standby mode and applies full power to the system. The system power LED changes from amber to green.

18. Do one of the following:
 - For tower models, install the bezel.
 - For rack models, if removed, install the security bezel.

After you replace the system board, you must re-enter the server serial number and the product ID.

1. During the server startup sequence, press the **F9** key to access RBSU.
2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warnings appear:

WARNING! WARNING! WARNING! The serial number is loaded into the system during the manufacturing process and should NOT be modified. This option should only be used by qualified service personnel. This value should always match the serial number sticker located on the chassis.

Warning: The serial number should ONLY be modified by qualified personnel. This value should always match the serial number located on the chassis.

5. Press the **Enter** key to clear the warning.
6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:
Warning: The Product ID should ONLY be modified by qualified personnel. This value should always match the Product ID on the chassis.
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server automatically reboots.

System battery

If the server no longer automatically displays the correct date and time, you might have to replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.



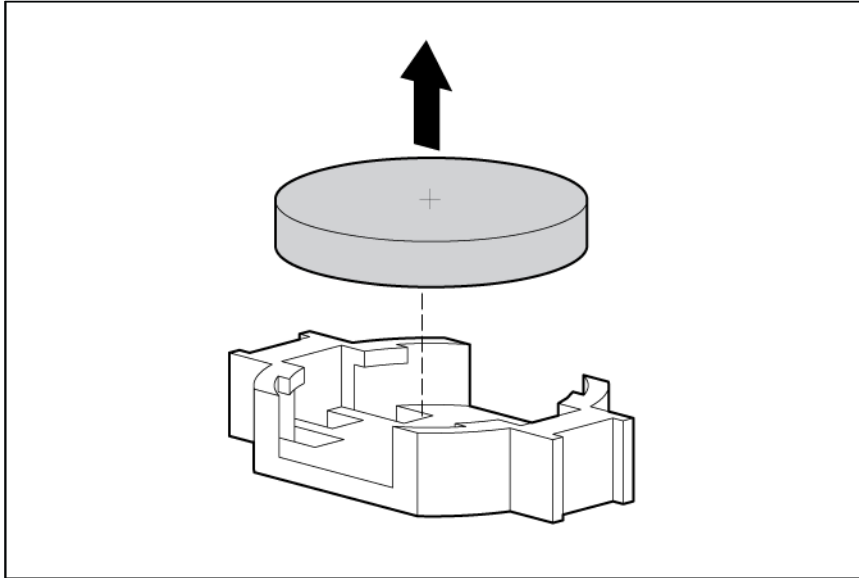
WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
- Replace only with the spare designated for this product.

To remove the component:

1. Do one of the following:
 - For tower models, open and remove the bezel ("[Remove the tower bezel](#)" on page 27).
 - For rack models, if installed, remove the security bezel (on page 27).
2. Power down the server (on page 26).
3. Remove all power:
 - a. Disconnect each power cord from the power source.
 - b. Disconnect each power cord from the server.
4. For tower models, do the following:
 - a. Place the server on a flat, level surface with the access panel facing up.
 - b. Remove the access panel ("[Access panel](#)" on page 29).
5. For rack models, do the following:
 - a. Extend the server from the rack (on page 28).
 - b. Remove the access panel ("[Access panel](#)" on page 29).
 - c. Release thumbscrews and remove the rack bezel.
6. Remove the air baffle ("[Air baffle](#)" on page 30).

7. Remove the battery.



IMPORTANT: Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, reconfigure the system through RBSU.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

HP Trusted Platform Module

The TPM is not a customer-removable part.



CAUTION: Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

If you suspect a TPM board failure, leave the TPM installed and remove the system board. Contact an HP authorized service provider for a replacement system board and TPM board.

Troubleshooting

Troubleshooting resources

The *HP ProLiant Gen8 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_TSG_v1_en)
- French (http://www.hp.com/support/ProLiant_TSG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_TSG_v1_sp)
- German (http://www.hp.com/support/ProLiant_TSG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_TSG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_TSG_v1_sc)

The *HP ProLiant Gen8 Troubleshooting Guide, Volume II: Error Messages* provides a list of error messages and information to assist with interpreting and resolving error messages on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_EMG_v1_en)
- French (http://www.hp.com/support/ProLiant_EMG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_EMG_v1_sp)
- German (http://www.hp.com/support/ProLiant_EMG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_EMG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_EMG_v1_sc)

Diagnostic tools

HP Insight Diagnostics

HP Insight Diagnostics is a proactive server management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, launch the SmartStart CD.

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server management. Available in Microsoft® Windows® and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, refer to the HP website (<http://www.hp.com/servers/diags>).

HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 75) provides survey functionality that gathers critical hardware and software information on ProLiant servers.

This functionality supports operating systems that may not be supported by the server. For operating systems supported by the server, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every SmartStart-assisted HP Insight Diagnostics installation, or it can be installed through the HP PSP.

NOTE: The current version of SmartStart provides the memory spare part numbers for the server. To download the latest version, see the HP website (<http://www.hp.com/support>).

Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within Survey Utility
- From within operating system-specific IML viewers
 - For NetWare: IML Viewer (does not apply to HP ProLiant DL980 Servers)
 - For Windows®: IML Viewer
 - For Linux: IML Viewer Application

- From within the iLO 4 user interface
- From within HP Insight Diagnostics (on page 75)

For more information, see the Management CD or DVD in the HP Insight Foundation suite for ProLiant.

HP Insight Remote Support software

HP strongly recommends that you install HP Insight Remote Support software to complete the installation or upgrade of your product and to enable enhanced delivery of your HP Warranty, HP Care Pack Service, or HP contractual support agreement. HP Insight Remote Support supplements your monitoring 24 x 7 to ensure maximum system availability by providing intelligent event diagnosis, and automatic, secure submission of hardware event notifications to HP, which will initiate a fast and accurate resolution, based on your product's service level. Notifications may be sent to your authorized HP Channel Partner for on-site service, if configured and available in your country. The software is available in two variants:

- **HP Insight Remote Support Standard:** This software supports server and storage devices and is optimized for environments with 1–50 servers. Ideal for customers who can benefit from proactive notification but do not need proactive service delivery and integration with a management platform.
- **HP Insight Remote Support Advanced:** This software provides comprehensive remote monitoring and proactive service support for nearly all HP servers, storage, network, and SAN environments, plus selected non-HP servers that have a support obligation with HP. It is integrated with HP Systems Insight Manager. A dedicated server is recommended to host both HP Systems Insight Manager and HP Insight Remote Support Advanced.

Details for both versions are available on the HP website (<http://www.hp.com/go/insightremotesupport>).

To download the software, go to Software Depot (<http://www.software.hp.com>).

Select **Insight Remote Support** from the menu on the right.

USB support

HP provides both standard USB 2.0 support and legacy USB 2.0 support. Standard support is provided by the OS through the appropriate USB device drivers. Before the OS loads, HP provides support for USB devices through legacy USB support, which is enabled by default in the system ROM.

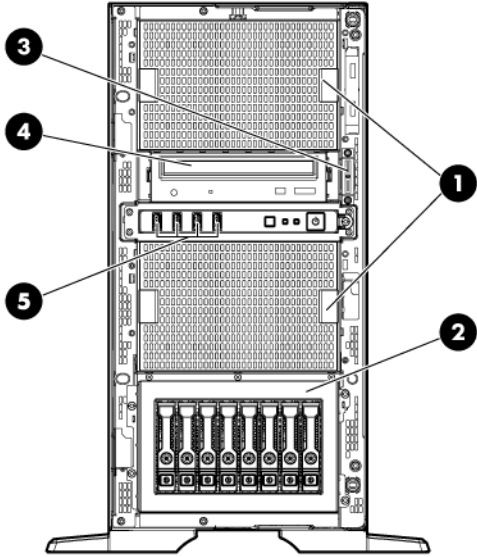
Legacy USB support provides USB functionality in environments where USB support is not available normally. Specifically, HP provides legacy USB functionality for the following:

- POST
- RBSU
- Diagnostics
- DOS
- Operating environments which do not provide native USB support

Component identification

Front panel components

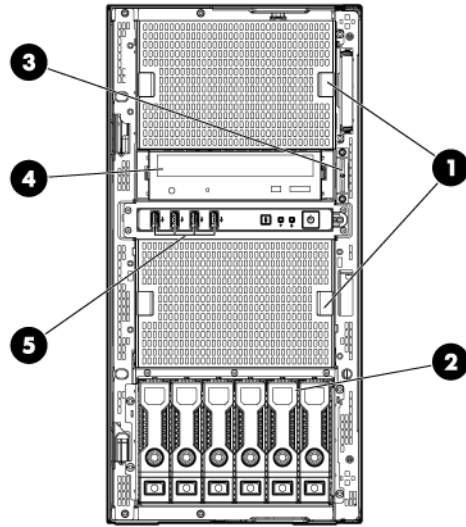
- SFF



Item	Description
1	Media/Drive cage bay
2	SAS/SATA drives (8)
3	Serial number/iLO information pull tab*
4	Optical drive
5	USB connectors (4)

*The serial number/iLO information pull tab is double-sided. The top side shows the server serial number, and the reverse side shows the default iLO account information. The same information is printed on a label attached to the chassis.

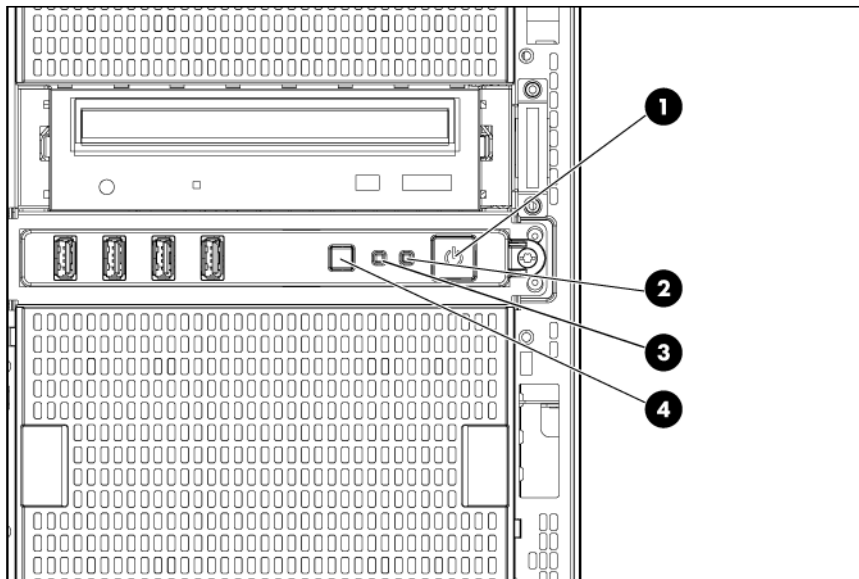
- LFF



Item	Description
1	Media/Drive cage bay
2	SAS/SATA drive (6)
3	Serial number/iLO information pull tab*
4	Optical drive
5	USB connectors (4)

*The serial number/iLO information pull tab is double-sided. The top side shows the server serial number, and the reverse side shows the default iLO account information. The same information is printed on a label attached to the chassis.

Front panel LEDs and buttons

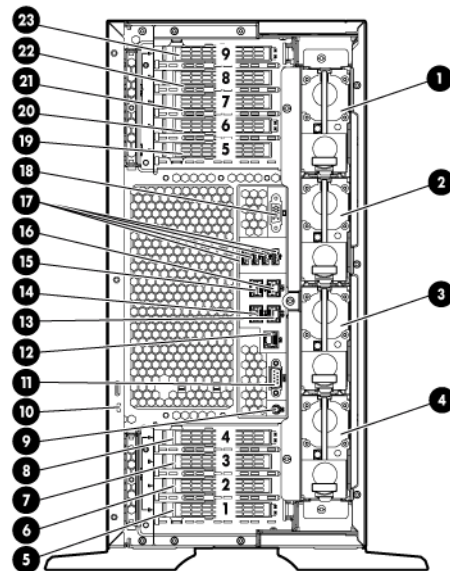


Item	Description	Status
1	Power On/Standby button and system power LED	Solid green = System on Flashing green (1 Hz/cycle per sec) = Performing power on sequence Solid amber = System in standby Off = No power present*
2	NIC status LED	Solid green = Link to network Flashing green (1 Hz/cycle per sec) = Network active Off = No network activity
3	Health LED	Solid green = Normal Flashing amber = System degraded Flashing red (1 Hz/cycle per sec) = System critical Fast-flashing red (4 Hz/cycles per sec) = Power fault**
4	UID button/LED	Solid blue = Activated Flashing blue (1 Hz/cycle per sec) = Remote management or firmware upgrade in progress Off = Deactivated

*Facility power is not present, power cord is not attached, no power supplies are installed, power supply failure has occurred, or the power button cable is disconnected.

**To identify components in a degraded or critical state, see the Systems Insight Display LEDs ("[Systems Insight Display assembly](#)" on page 53), check iLO/BIOS logs, and reference the server troubleshooting guide.

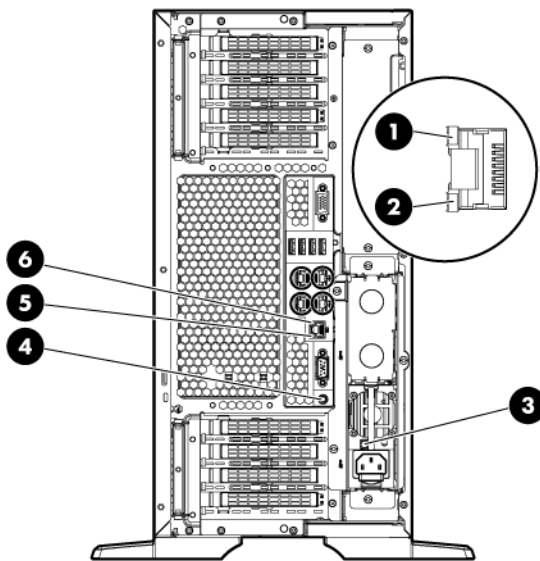
Rear panel components



Item	Description
1	Power supply 4
2	Power supply 3
3	Power supply 2
4	Power supply 1
5	PCIe slot 1 (Processor 1)
6	PCIe slot 2 (Processor 1)
7	PCIe slot 3 (Processor 1)

Item	Description
8	PCIe slot 4 (Processor 1)
9	UID button/LED
10	Kensington security lock
11	Serial connector
12	iLO connector
13	NIC connector 3
14	NIC connector 4
15	NIC connector 2
16	NIC connector 1
17	USB connectors (4)
18	Video connector
19	PCIe slot 5 (Processor 2)
20	PCIe slot 6 (Processor 2)
21	PCIe slot 7 (Processor 2)
22	PCIe slot 8 (Processor 2)
23	PCIe slot 9 (Processor 2)

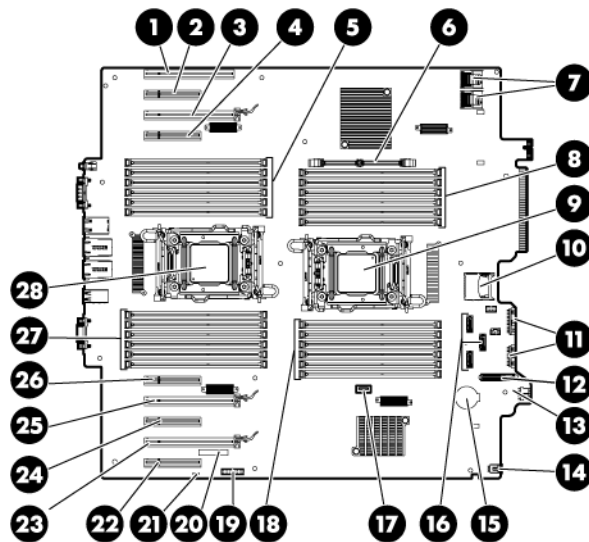
Rear panel LEDs



Item	Description	Status
1	NIC activity LED	Green or flashing green = Network activity Off = No network activity
2	NIC link LED	Green = Linked to network Off = No network connection

Item	Description	Status
3	Power supply LED	Green = Normal Off = One or more of the following conditions exists: <ul style="list-style-type: none"> • Power is unavailable. • Power supply failed. • Power supply is in standby mode. • Power supply exceeded current limit.
4	UID LED	Blue = Activated Flashing blue = System is being managed remotely Off = Deactivated
5	iLO 4 link LED	Green = Linked to network Off = No network connection
6	iLO 4 activity LED	Green or flashing green = Network activity Off = No network activity

System board components



Item	Description
1	Slot 1 PCIe3 x16 (8, 4, 1)
2	Slot 2 PCIe3 x8 (4, 1)
3	Slot 3 PCIe3 x16 (16, 8, 4, 1)
4	Slot 4 PCIe3 x8 (4, 1)
5	Processor 1 DIMM slots
6	Smart Array P420i memory cache module
7	Mini-SAS connectors (2)
8	Processor 2 DIMM slots
9	Processor socket 2
10	SD card slot
11	Front panel connectors (2)
12	Fan cage connector

Item	Description
13	Internal USB tape connector
14	Discovery service cable connector
15	System battery
16	SATA connectors
17	Internal USB connector
18	Processor 2 DIMM slots
19	TPM connector
20	System maintenance switch
21	NMI header
22	Slot 9 PCIe3 x8 (4, 1)
23	Slot 8 PCIe3 x16 (16, 8, 4, 1)
24	Slot 7 PCIe3 x8 (4, 1)
25	Slot 6 PCIe3 x16 (16, 8, 4, 1)
26	Slot 5 PCIe2 x8 (4, 1)
27	Processor 1 DIMM slots
28	Processor socket 1 (populated)

System maintenance switch

Position	Default	Function
S1	Off	Off = iLO 4 security is enabled. On = iLO 4 security is disabled.
S2	Off	Off = System configuration can be changed. On = System configuration is locked.
S3	Off	Reserved
S4	Off	Reserved
S5	Off	Off = Power-on password is enabled. On = Power-on password is disabled.
S6	Off	Off = No function On = ROM reads system configuration as invalid.
S7	—	Reserved
S8	—	Reserved
S9	—	Reserved
S10	—	Reserved
S11	—	Reserved
S12	—	Reserved

To access the redundant ROM, set S1, S5, and S6 to on.

When the system maintenance switch position 6 is set to the On position, the system is prepared to erase all system configuration settings from both CMOS and NVRAM.



CAUTION: Clearing CMOS and/or NVRAM deletes configuration information. Be sure to properly configure the server or data loss could occur.

NMI functionality

An NMI crash dump creates a crash dump log before resetting a system which is not responding.

Crash dump log analysis is an essential part of diagnosing reliability problems, such as failures of operating systems, device drivers, and applications. Many crashes freeze a system, and the only available action for administrators is to restart the system. Resetting the system erases any information which could support problem analysis, but the NMI feature preserves that information by performing a memory dump before a system reset.

To force the system to invoke the NMI handler and generate a crash dump log, do one of the following:

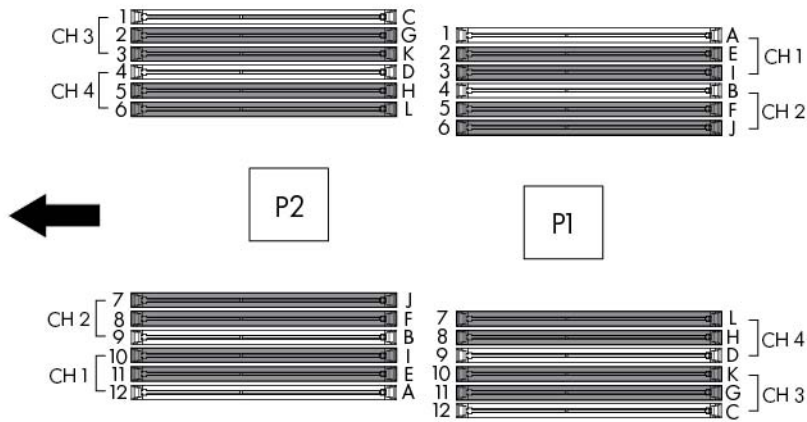
- Use the iLO Virtual NMI feature.
- Short the NMI header ("System board components" on page 81).

For more information, see the HP website (<http://www.hp.com/support/NMI>).

DIMM slots

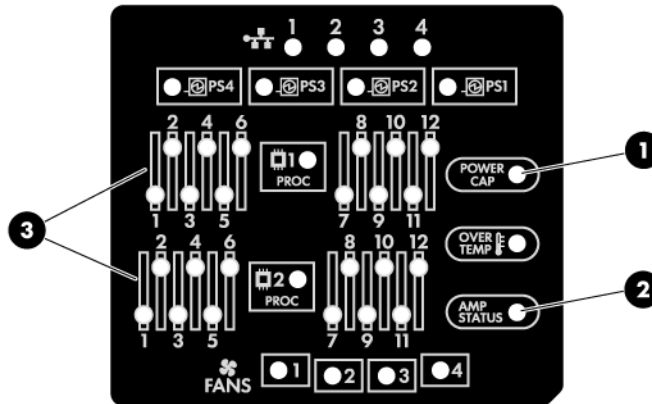
DIMM slots are numbered sequentially (1 through 12) for each processor. The supported AMP modes use the letter assignments for population guidelines.

NOTE: For proper orientation, the arrow indicates the front of the server.



Systems Insight Display LEDs

The HP Systems Insight Display LEDs represent the system board layout.



Item	Description	Status
1	Power cap	To determine Power cap status, see "Systems Insight Display LED combinations (on page 84)."
2	AMP Status	Green = AMP mode enabled Amber = Failover Off = AMP mode disabled
3	DIMM LEDs	Amber = DIMM error Off = Normal
	All other LEDs	Amber = Failure Off = Normal



IMPORTANT: If more than one DIMM slot LED is illuminated, further troubleshooting is required. Test each bank of DIMMs by removing all other DIMMs. Isolate the failed DIMM by replacing each DIMM in a bank with a known working DIMM.

Systems Insight Display LED combinations

When the health LED on the front panel illuminates either amber or red, the server is experiencing a health event. Combinations of illuminated Systems Insight Display LEDs, the system power LED, and the health LED indicate system status.

Systems Insight Display LED and color	Health LED	System power LED	Status
Processor (amber)	Red	Amber	One or more of the following conditions might exist: <ul style="list-style-type: none"> • Processor in socket X has failed. • Processor X is not installed in the socket. • Processor X is unsupported. • ROM detects a failed processor during POST
Processor (amber)	Amber	Green	Processor in socket X is in a pre-failure condition.
DIMM (amber)	Red	Green	One or more DIMMs have failed.
DIMM (amber)	Amber	Green	DIMM in slot X is in a pre-failure condition.
Overtemperature (amber)	Amber	Green	The Health Driver has detected a cautionary temperature level.
Overtemperature (amber)	Red	Amber	The server has detected a hardware critical temperature level.
Fan (amber)	Amber	Green	Fan has failed or is missing, but still meets the minimum fan requirements.
Fan (amber)	Red	Green	Fan has failed or is missing and no longer meets the minimum fan requirements.
Power supply (amber)	Red	Amber	<ul style="list-style-type: none"> • Only one power supply installed and in standby mode. • Power supply fault • System board fault
Power supply (amber)	Amber	Green	<ul style="list-style-type: none"> • Redundant power supply is installed and only one power supply is functional. • AC power cord is not plugged into redundant power supply. • Redundant power supply fault • Power supply mismatch at POST or through hot-plug addition.
Power cap (off)	—	Amber	Standby
Power cap (green)	—	Flashing green	Waiting for power
Power cap (flashing amber)	—	Amber	Power cap has been exceeded
Power cap (green)	—	Green	Power is available



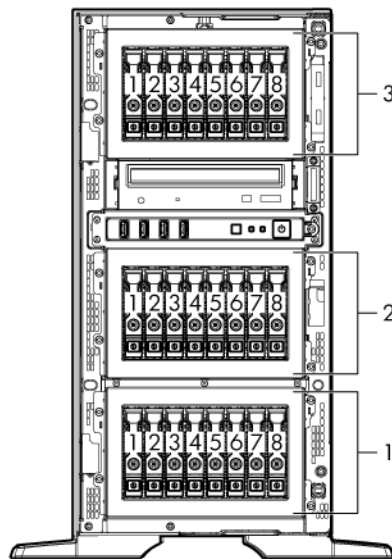
IMPORTANT: If more than one DIMM slot LED is illuminated, further troubleshooting is required. Test each bank of DIMMs by removing all other DIMMs. Isolate the failed DIMM by replacing each DIMM in a bank with a known working DIMM.

SAS and SATA device numbers

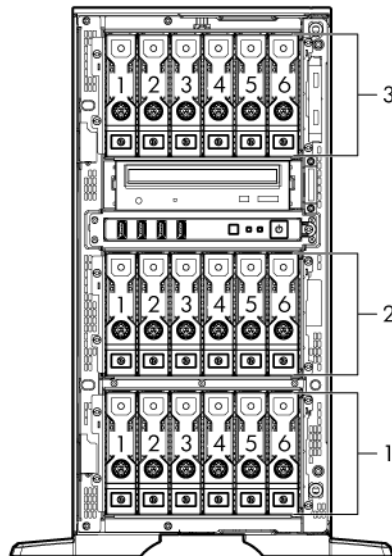
With optional drive cages installed, the server supports up to 24 SFF drives or up to 18 LFF drives. The server does not support mixing SFF and LFF drives.

HP recommends that you populate drive bays starting with the lowest SAS or SATA device number. Drives are numbered from left to right in each component box. Component boxes are numbered 1 through 3, from bottom to top.

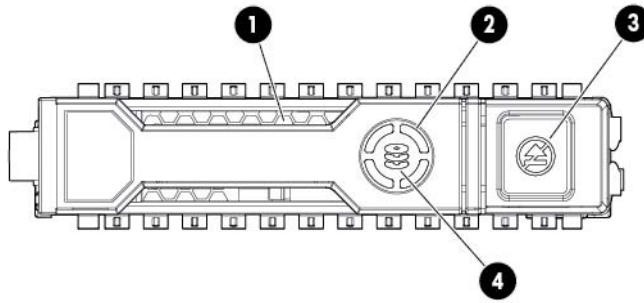
- SFF drives



- LFF drives



Hot-plug drive LED definitions

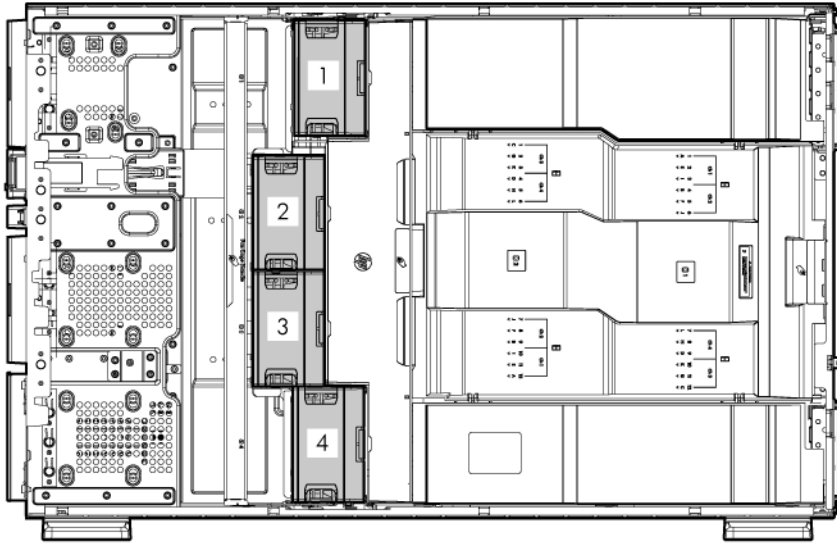


Item	LED	Status	Definition
1	Locate	Solid blue	The drive is being identified by a host application.
		Flashing blue	The drive carrier firmware is being updated or requires an update.
2	Activity ring	Rotating green	Drive activity
		Off	No drive activity
3	Do not remove	Solid white	Do not remove the drive. Removing the drive causes one or more of the logical drives to fail.
		Off	Removing the drive does not cause a logical drive to fail.
4	Drive status	Solid green	The drive is a member of one or more logical drives.
		Flashing green	The drive is rebuilding or performing a RAID migration, strip size migration, capacity expansion, or logical drive extension, or is erasing.
		Flashing amber/green	The drive is a member of one or more logical drives and predicts the drive will fail.
		Flashing amber	The drive is not configured and predicts the drive will fail.
		Solid amber	The drive has failed.
		Off	The drive is not configured by a RAID controller.

Fans



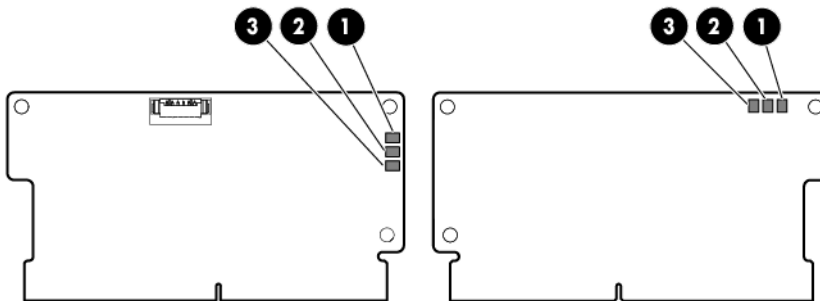
IMPORTANT: Fan louvers must be present for the redundant configuration. Without the louvers, all four fans are nonredundant.



Item	Description	Configuration
1	Fan 1	Redundant (primary fan when processor 2 is installed)
2	Fan 2	Primary
3	Fan 3	Primary
4	Fan 4	Primary

FBWC module LEDs (P222, P420, P420i, P421, P822)

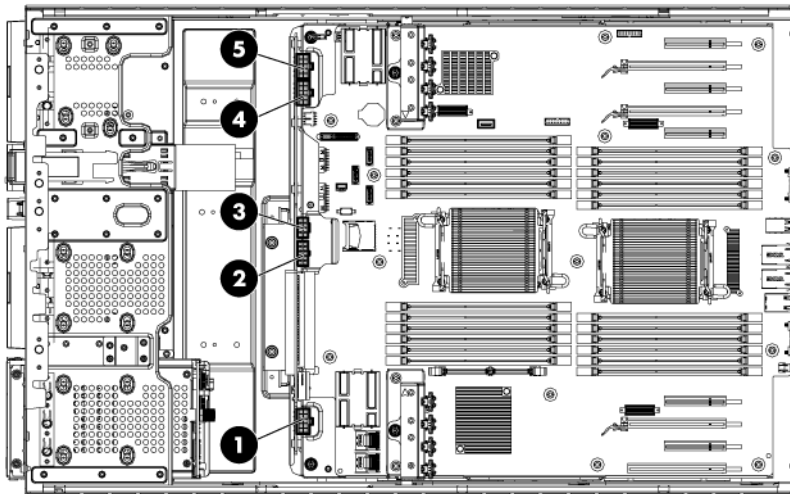
The FBWC module has three single-color LEDs (one amber and two green). The LEDs on the cache module installed on a storage controller are duplicated on the reverse side of the module to facilitate status viewing.



1 - Amber	2 - Green	3 - Green	Interpretation
Off	Off	Off	The cache module is not powered.

1 - Amber	2 - Green	3 - Green	Interpretation
Off	Flashing 0.5 Hz	Flashing 0.5 Hz	The cache microcontroller is executing from within its boot loader and receiving new flash code from the host controller.
Off	Flashing 1 Hz	Flashing 1 Hz	The cache module is powering up, and the capacitor pack is charging.
Off	Off	Flashing 1 Hz	The cache module is idle, and the capacitor pack is charging.
Off	Off	On	The cache module is idle, and the capacitor pack is charged.
Off	On	On	The cache module is idle, the capacitor pack is charged, and the cache contains data that has not yet been written to the drives.
Off	Flashing 1 Hz	Off	A backup is in progress.
Off	On	Off	The current backup is complete with no errors.
Flashing 1 Hz	Flashing 1 Hz	Off	The current backup failed, and data has been lost.
Flashing 1 Hz	Flashing 1 Hz	On	A power error occurred during the previous or current boot. Data might be corrupt.
Flashing 1 Hz	On	Off	An overtemperature condition exists.
Flashing 2 Hz	Flashing 2 Hz	Off	The capacitor pack is not attached.
Flashing 2 Hz	Flashing 2 Hz	On	The capacitor has been charging for 10 minutes, but has not reached sufficient charge to perform a full backup.
On	On	Off	The current backup is complete, but power fluctuations occurred during the backup.
On	On	On	The cache module microcontroller has failed.

RPS riser board connectors

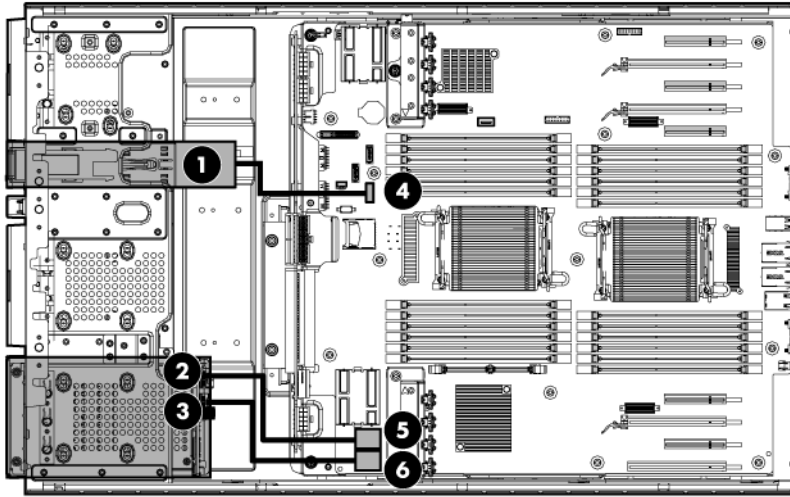


Item	Connector	Description
1	J7	Graphic card power connector

Item	Connector	Description
2	J9	Drive backplane bay 1/optical drive power connector
3	J5	Drive backplane bay 2 power connector
4	J6	Drive backplane bay 3 power connector
5	J8	Graphic card power connector

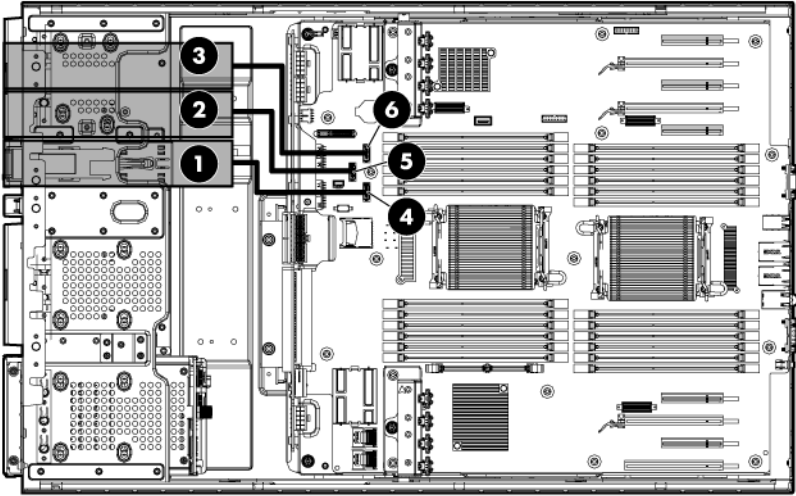
Cabling

Server data cabling



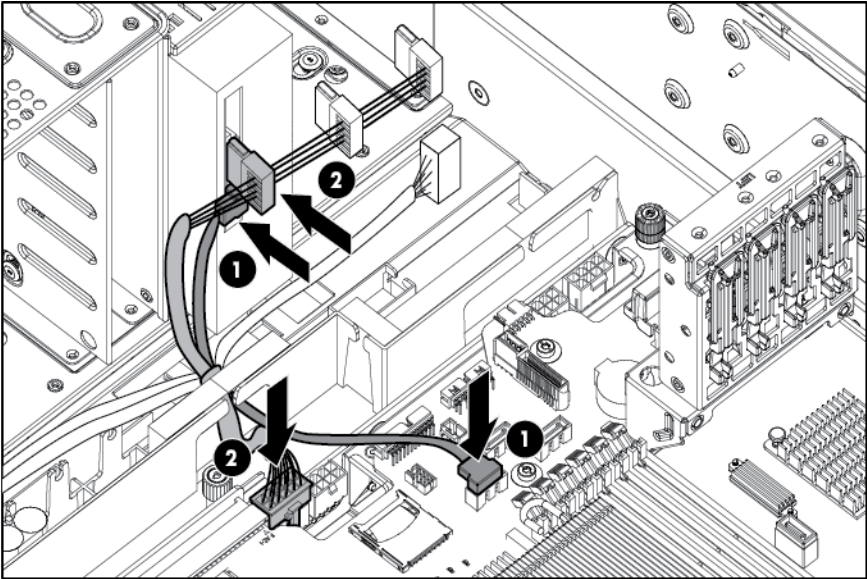
Item	Description
1	Optical drive connector
2	Drive cage 1, SAS connector 2
3	Drive cage 1, SAS connector 1
4	SATA connector
5	SAS connector
6	SAS connector

Media device data cabling



Item	Description
1	Optical drive connector
2	Optical drive connector
3	Optical drive connector
4	SATA connector
5	SATA connector
6	SATA connector

Optical drive cabling



Specifications

Environmental specifications

Specification	Value
Temperature range*	
Operating	10°C to 35°C (50°F to 95°F)
Nonoperating	-30°C to 60°C (-22°F to 140°F)
Relative humidity (noncondensing)	
Operating, maximum wet bulb temperature of 28°C (82.4°F)	10% to 90%
Nonoperating, maximum wet bulb temperature of 38.7°C (101.7°F)	5% to 95%

* All temperature ratings shown are for sea level. An altitude derating of 1°C per 304.8 m (1.8°F per 1,000 ft) to 3048 m (10,000 ft) is applicable. No direct sunlight allowed.

Server specifications

Specification	Value
Dimensions	
Rack model	—
Height	21.8 cm (8.58 in)
Depth	73.22 cm (28.83 in)
Width	48.26 cm (19.00 in)
Tower model	—
Height	46.2 cm (18.19 in)
Depth	74.00 cm (29.13 in)
Width	21.8 cm (8.58 in)
Weight	
Rack model	—
Maximum	50.06 kg (110.36 lbs)
Minimum	27.63 kg (60.91 lbs)
Tower model	—
Maximum	52.09 kg (114.84 lbs)
Minimum	31.09 kg (70.33 lbs)

Power supply specifications

Depending on installed options, the server is configured with one of the following power supplies:

- HP 460 W Gold Power Supply (92% efficiency)
- HP 460 W Platinum Plus Power Supply (94% efficiency)
- HP 750 W Gold Power Supply (92% efficiency)
- HP 750 W Platinum Plus Power Supply (94% efficiency)
- HP 1200 W Platinum Plus Power Supply (94% efficiency)

HP 460 W Gold Power Supply (92% efficiency)

Specification	Value
Input requirements	—
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	5.5 A at 100 VAC 2.6 A at 200 VAC
Rated input power	526 W at 100V AC input 505 W at 200V AC input
Btus per hour	1794 at 100V AC input 1725 at 200V AC input
Power supply output	—
Rated steady-state power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input
Maximum peak power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input

HP 460 W Platinum Plus Power Supply (94% efficiency)

Specification	Value
Input requirements	—
Rated input voltage	100 to 240 VAC
Rated input frequency	47 Hz to 63 Hz
Rated input current	8 A
Rated input power	509 W at 115V AC input 495 W at 230V AC input
Btus per hour	1764 at 100V AC input 1736 at 115V AC input 1694 at 200V AC input 1687 at 230V AC input
Power supply output	—
Rated steady-state power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input
Maximum peak power	460 W at 100V to 120V AC input 460 W at 200V to 240V AC input

HP 750 W Gold Power Supply (92% efficiency)

Specification	Value
Input requirements	—
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	8.9 A at 100 VAC 4.3 A at 200 VAC
Rated input power	857 W at 100V AC input 824 W at 200V AC input
Btus per hour	2925 at 100V AC input 2812 at 200V AC input
Power supply output	—
Rated steady-state power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input
Maximum peak power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input

HP 750 W Platinum Plus Power Supply (94% efficiency)

Specification	Value
Input requirements	—
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz
Rated input current	8.5 A at 100 VAC 4.1 A at 200 VAC
Rated input power	831 W at 115V AC input 808 W at 230V AC input
Btus per hour	2878 at 100V AC input 2834 at 115V AC input 2769 at 200V AC input 2758 at 230V AC input
Power supply output	—
Rated steady-state power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input
Maximum peak power	750 W at 100V to 120V AC input 750 W at 200V to 240V AC input

HP 1200 W Platinum Plus Power Supply (94% efficiency)

Specification	Value
Input requirements	—
Rated input voltage	100 to 120 VAC, 200 to 240 VAC
Rated input frequency	50 Hz to 60 Hz

Rated input current	10 A at 100 VAC 6.7 A at 200 VAC
Rated input power	990 W at 115V AC input 1315 W at 230V AC input
Btus per hour	3060 at 100V AC input 3380 at 115V AC input 4503 at 200V AC input 4485 at 230V AC input
Power supply output	—
Rated steady-state power	800 W at 100V AC input 900 W at 120V AC input 1200 W at 200V to 240V AC input
Maximum peak power	800 W at 100V AC input 900 W at 120V AC input 1200 W at 200V to 240V AC input

Acronyms and abbreviations

AMP

Advanced Memory Protection

CS HE

HP Common Slot High-Efficiency (power supply)

CSR

Customer Self Repair

FBWC

flash-backed write cache

iLO

Integrated Lights-Out

IML

Integrated Management Log

LFF

large form factor

LRDIMM

load reduced dual in-line memory module

NMI

nonmaskable interrupt

NVRAM

nonvolatile memory

ORCA

Option ROM Configuration for Arrays

PCIe

Peripheral Component Interconnect Express

POST

Power-On Self Test

PSP

HP ProLiant Support Pack

RBSU

ROM-Based Setup Utility

RPS

redundant power supply

SAS

serial attached SCSI

SATA

serial ATA

SFF

small form factor

SID

Systems Insight Display

SIM

Systems Insight Manager

TPM

Trusted Platform Module

UID

unit identification

USB

universal serial bus

Documentation feedback

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